

LOW NOISE, HIGH SLEW RATE, UNITY GAIN STABLE VOLTAGE FEEDBACK AMPLIFIER

FEATURES

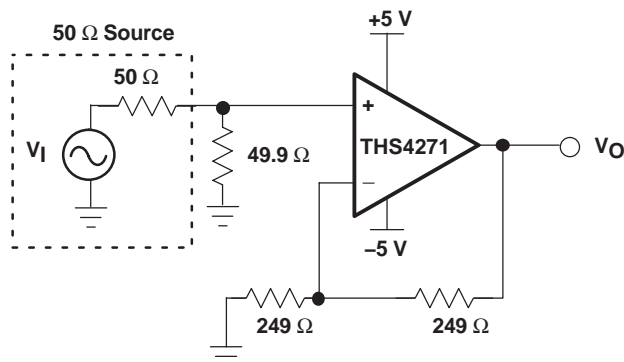
- Unity Gain Stability
- Low Voltage Noise
 - 3 nV/ $\sqrt{\text{Hz}}$
- High Slew Rate: 1000 V/ μs
- Low Distortion
 - -92 dBc THD at 30 MHz
- Wide Bandwidth: 1.4 GHz
- Supply Voltages
 - +5 V, ± 5 V, +12 V, +15 V
- Power Down Functionality (THS4275)
- Evaluation Module Available

DESCRIPTION

The THS4271 and THS4275 are low-noise, high slew rate, unity gain stable voltage feedback amplifiers designed to run from supply voltages as low as 5 V and as high as 15 V. The THS4275 offers the same performance as the THS4271 with the addition of power down capability. The combination of low-noise, high slew rate, wide bandwidth, low distortion, and unity gain stability make the THS4271 and THS4275 high performance devices across multiple ac specifications.

Designers using the THS4271 are rewarded with higher dynamic range over a wider frequency band without the stability concerns of decompensated amplifiers. The devices are available in SOIC, MSOP with PowerPAD™, and leadless MSOP with PowerPAD™ packages.

Low-Noise, Low-Distortion, Wideband Application Circuit



NOTE: Power supply decoupling capacitors not shown

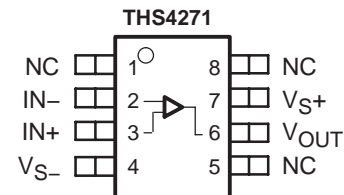


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

APPLICATIONS

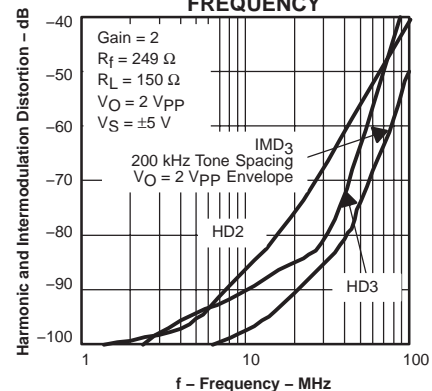
- High Linearity ADC Preamplifier
- Wireless Communication Receivers
- Differential to Single-Ended Conversion
- DAC Output Buffer
- Active Filtering



RELATED DEVICES

DEVICE	DESCRIPTION
THS4211	1-GHz voltage feedback amplifier
THS4503	Wideband fully differential amplifier
THS3202	Dual, wideband current feedback amplifier

HARMONIC AND INTERMODULATION DISTORTION vs FREQUENCY



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted⁽¹⁾

	UNIT	
Supply voltage, V_S	16.5 V	
Input voltage, V_I	$\pm V_S$	
Output current, I_O	100 mA	
Continuous power dissipation	See Dissipation Rating Table	
Maximum junction temperature, T_J	150°C	
Maximum junction temperature, continuous operation, long term reliability $T_{J(2)}$	125°C	
Storage temperature range, T_{stg}	-65°C to 150°C	
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	300°C	
ESD ratings:	HBM	3000 V
	CDM	1500 V
	MM	1000 V

(1) The absolute maximum temperature under any condition is limited by the constraints of the silicon process. Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) The maximum junction temperature for continuous operation is limited by package constraints. Operation above this temperature may result in reduced reliability and/or lifetime of the device.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE DISSIPATION RATINGS

PACKAGE	θ_{JC} (°C/W)	θ_{JA} ⁽¹⁾ (°C/W)	POWER RATING ⁽²⁾	
			$T_A \leq 25^\circ\text{C}$	$T_A = 85^\circ\text{C}$
D (8 pin)	38.3	97.5	1.02 W	410 mW
DGN (8 pin) ⁽³⁾	4.7	58.4	1.71 W	685 mW
DGK (8 pin)	54.2	260	385 mW	154 mW
DRB (8 pin) ⁽³⁾	5	45.8	2.18 W	873 mW

(1) This data was taken using the JEDEC standard High-K test PCB.

(2) Power rating is determined with a junction temperature of 125°C. This is the point where distortion starts to substantially increase. Thermal management of the final PCB should strive to keep the junction temperature at or below 125°C for best performance and long term reliability.

(3) The THS4271/5 may incorporate a PowerPAD™ on the underside of the chip. This acts as a heat sink and must be connected to a thermally dissipative plane for proper power dissipation. Failure to do so may result in exceeding the maximum junction temperature which could permanently damage the device. See TI technical briefs SLMA002 and SLMA004 for more information about utilizing the PowerPAD thermally enhanced package.

RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
Supply voltage, (V_{S+} and V_{S-})	Dual supply	± 2.5	V
	Single supply	5	
Input common-mode voltage range	$V_{S-} + 1.4$	$V_{S+} - 1.4$	V

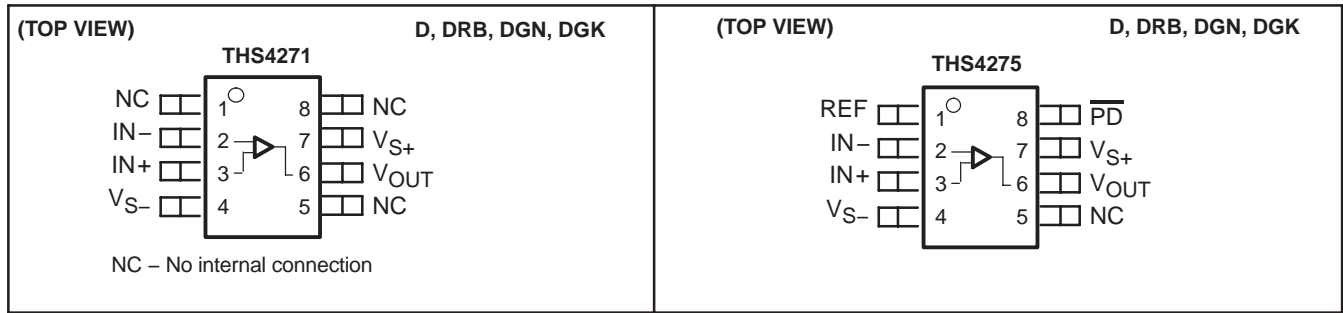
PACKAGING/ORDERING INFORMATION

ORDERABLE PACKAGE AND NUMBER					
PLASTIC SMALL OUTLINE (D) ⁽¹⁾	LEADLESS MSOP 8 ⁽²⁾	PLASTIC MSOP ⁽¹⁾ PowerPAD		PLASTIC MSOP ⁽¹⁾	
	(DRB)	(DGN)	PACKAGE MARKING	(DGK)	PACKAGE MARKING
THS4271D	THS4271DRBT	THS4271DGN	BFQ	THS4271DGK	BEY
THS4271DR	THS4271DRBR	THS4271DGNR		THS4271DGKR	
THS4275D	THS4275DRBT	THS4275DGN	BFR	THS4275DGK	BJD
THS4275DR	THS4275DRBR	THS4275DGNR		THS4275DGKR	

(1) All packages are available taped and reeled. The R suffix standard quantity is 2500 (e.g., THS4271DGNR).

(2) All packages are available taped and reeled. The R suffix standard quantity is 3000. The T suffix standard quantity is 250 (e.g., THS4271DRBT).

PIN ASSIGNMENTS



ELECTRICAL CHARACTERISTICS $V_S = \pm 5\text{ V}$

$R_F = 249\ \Omega$, $R_L = 499\ \Omega$, $G = +2$, unless otherwise noted.

PARAMETER	TEST CONDITIONS	TYP	OVER TEMPERATURE			UNITS	MIN/ TYP/ MAX
		25°C	25°C	0°C TO 70°C	-40°C TO 85°C		
AC PERFORMANCE							
Small signal bandwidth	$G = 1, V_O = 100\text{ mV}_{PP}, R_L = 150\ \Omega$	1.4				GHz	Typ
	$G = -1, V_O = 100\text{ mV}_{PP}$	400				MHz	Typ
	$G = 2, V_O = 100\text{ mV}_{PP}$	390				MHz	Typ
	$G = 5, V_O = 100\text{ mV}_{PP}$	85				MHz	Typ
	$G = 10, V_O = 100\text{ mV}_{PP}$	40				MHz	Typ
0.1 dB flat bandwidth	$G = 1, V_O = 100\text{ mV}_{PP}, R_L = 150\ \Omega$	200				MHz	Typ
Gain bandwidth product	$G > 10, f = 1\text{ MHz}$	400				MHz	Typ
Full-power bandwidth	$G = -1, V_O = 2\text{ V}_P$	80				MHz	Typ
Slew rate	$G = 1, V_O = 2\text{ V Step}$	950				V/ μ s	Typ
	$G = -1, V_O = 2\text{ V Step}$	1000				V/ μ s	Typ
Settling time to 0.1%	$G = -1, V_O = 4\text{ V Step}$	25				ns	Typ
Settling time to 0.01%	$G = -1, V_O = 4\text{ V Step}$	38				ns	Typ
Harmonic distortion	$G = 1, V_O = 1\text{ V}_{PP}, f = 30\text{ MHz}$						
Second harmonic distortion	$R_L = 150\ \Omega$	-92				dBc	Typ
	$R_L = 499\ \Omega$	-80				dBc	Typ
Third harmonic distortion	$R_L = 150\ \Omega$	-95				dBc	Typ
	$R_L = 499\ \Omega$	-95				dBc	Typ
Harmonic distortion	$G = 2, V_O = 2\text{ V}_{PP}, f = 30\text{ MHz}$						
Second harmonic distortion	$R_L = 150\ \Omega$	-65				dBc	Typ
	$R_L = 499\ \Omega$	-70				dBc	Typ
Third harmonic distortion	$R_L = 150\ \Omega$	-80				dBc	Typ
	$R_L = 499\ \Omega$	-90				dBc	Typ
Third order intermodulation (IMD ₃)	$G = 2, V_O = 2\text{ V}_{PP}, R_L = 150\ \Omega,$ $f = 70\text{ MHz}$	-60				dBc	Typ
Third order output intercept (OIP ₃)	$G = 2, V_O = 2\text{ V}_{PP}, R_L = 150\ \Omega,$ $f = 70\text{ MHz}$	35				dBm	Typ
Differential gain (NTSC, PAL)	$G = 2, R_L = 150\ \Omega,$	0.007%					Typ
Differential phase (NTSC, PAL)	$G = 2, R_L = 150\ \Omega,$	0.004				°	Typ
Input voltage noise	$f = 1\text{ MHz}$	3				nV/ $\sqrt{\text{Hz}}$	Typ
Input current noise	$f = 1\text{ MHz}$	3				pA/ $\sqrt{\text{Hz}}$	Typ

ELECTRICAL CHARACTERISTICS $V_S = \pm 5\text{ V}$ (continued)

$R_F = 249\ \Omega$, $R_L = 499\ \Omega$, $G = +2$, unless otherwise noted.

PARAMETER	TEST CONDITIONS	TYP	OVER TEMPERATURE				MIN/ TYP/ MAX
		25°C	25°C	0°C to 70°C	-40°C to 85°C	UNITS	
DC PERFORMANCE							
Open-loop voltage gain (A_{OL})	$V_O = \pm 50\text{ mV}$, $R_L = 499\ \Omega$	75	65	60	60	dB	Min
Input offset voltage	$V_{CM} = 0\text{ V}$	5	10	12	12	mV	Max
Average offset voltage drift	$V_{CM} = 0\text{ V}$			± 10	± 10	$\mu\text{V}/^\circ\text{C}$	Typ
Input bias current	$V_{CM} = 0\text{ V}$	6	15	18	18	μA	Max
Average bias current drift	$V_{CM} = 0\text{ V}$			± 10	± 10	$\text{nA}/^\circ\text{C}$	Typ
Input offset current	$V_{CM} = 0\text{ V}$	1	6	8	8	μA	Max
Average offset current drift	$V_{CM} = 0\text{ V}$			± 10	± 10	$\text{nA}/^\circ\text{C}$	Typ
INPUT CHARACTERISTICS							
Common-mode input range		± 4	± 3.6	± 3.5	± 3.5	V	Min
Common-mode rejection ratio	$V_{CM} = \pm 2\text{ V}$	72	67	65	65	dB	Min
Input resistance	Common-mode	5				M Ω	Typ
Input capacitance	Common-mode / differential	0.4/0.8				pF	Typ
OUTPUT CHARACTERISTICS							
Output voltage swing	$G = +2$	± 4	± 3.8	± 3.7	± 3.7	V	Min
Output current (sourcing)	$R_L = 10\ \Omega$	160	120	110	110	mA	Min
Output current (sinking)	$R_L = 10\ \Omega$	80	60	50	50	mA	Min
Output impedance	$f = 1\text{ MHz}$	0.1				Ω	Typ
POWER SUPPLY							
Specified operating voltage		± 5	± 7.5	± 7.5	± 7.5	V	Max
Maximum quiescent current		22	24	27	28	mA	Max
Minimum quiescent current		22	20	18	15	mA	Min
Power supply rejection (+PSRR)	$V_{S+} = 5.5\text{ V}$ to 4.5 V , $V_{S-} = 5\text{ V}$	85	75	70	70	dB	Min
Power supply rejection (-PSRR)	$V_{S+} = 5\text{ V}$, $V_{S-} = -5.5\text{ V}$ to -4.5 V	75	65	60	60	dB	Min
POWER-DOWN CHARACTERISTICS (THS4275 only)							
Power-down voltage level ⁽¹⁾	REF = 0 V, or V_{S-}	Enable		REF+1.8		V	Min
		Power down		REF+1		V	Max
	REF = V_{S+} or Floating	Enable		REF-1		V	Min
		Power down		REF-1.7		V	Max
Power-down quiescent current	PD = Ref +1.0 V, Ref = 0 V	875	1000	1100	1200	μA	Max
	PD = Ref -1.7 V, Ref = V_{S+}	650	800	900	1000	μA	Max
Turnon time delay (t_{ON})	50% of final supply current value	4				μs	Typ
Turnoff time delay (t_{OFF})	50% of final supply current value	3				μs	Typ
Input impedance	$f = 1\text{ MHz}$	4				G Ω	Typ
Output impedance		200				k Ω	Typ

(1) For detail information on the power-down circuit, see the powerdown section in the application information of this data sheet.

ELECTRICAL CHARACTERISTICS $V_S = 5\text{ V}$

$R_F = 249\ \Omega$, $R_L = 499\ \Omega$, $G = +2$, unless otherwise noted

PARAMETER	TEST CONDITIONS	TYP	OVER TEMPERATURE				MIN/ TYP/ MAX
		25°C	25°C	0°C to 70°C	-40°C to 85°C	UNITS	
AC PERFORMANCE							
Small signal bandwidth	$G = 1$, $V_O = 100\text{ mV}_{PP}$, $R_L = 150\ \Omega$	1.2				GHz	Typ
	$G = -1$, $V_O = 100\text{ mV}_{PP}$	380				MHz	Typ
	$G = 2$, $V_O = 100\text{ mV}_{PP}$	360				MHz	Typ
	$G = 5$, $V_O = 100\text{ mV}_{PP}$	80				MHz	Typ
	$G = 10$, $V_O = 100\text{ mV}_{PP}$	35				MHz	Typ
0.1-dB flat bandwidth	$G = 1$, $V_O = 100\text{ mV}_{PP}$, $R_L = 150\ \Omega$	120				MHz	Typ
Gain bandwidth product	$G > 10$, $f = 1\text{ MHz}$	350				MHz	Typ
Full-power bandwidth	$G = -1$, $V_O = 2\text{ V}_P$	60				MHz	Typ
Slew rate	$G = 1$, $V_O = 2\text{ V Step}$	700				V/ μs	Typ
	$G = -1$, $V_O = 2\text{ V Step}$	750				V/ μs	Typ
Settling time to 0.1%	$G = -1$, $V_O = 2\text{ V Step}$	18				ns	Typ
Settling time to 0.01%	$G = -1$, $V_O = 2\text{ V Step}$	66				ns	Typ
Harmonic distortion	$G = 1$, $V_O = 1\text{ V}_{PP}$, $f = 30\text{ MHz}$						
Second harmonic distortion	$R_L = 150\ \Omega$	-75				dBc	Typ
	$R_L = 499\ \Omega$	-72				dBc	Typ
Third harmonic distortion	$R_L = 150\ \Omega$	-70				dBc	Typ
	$R_L = 499\ \Omega$	-70				dBc	Typ
Third order intermodulation (IMD ₃)	$G = 2$, $V_O = 1\text{ V}_{PP}$, $R_L = 150\ \Omega$, $f = 70\text{ MHz}$	-65				dBc	Typ
Third order output intercept (OIP ₃)	$G = 2$, $V_O = 1\text{ V}_{PP}$, $R_L = 150\ \Omega$, $f = 70\text{ MHz}$	32				dBm	Typ
Input voltage noise	$f = 1\text{ MHz}$	3				nV/ $\sqrt{\text{Hz}}$	Typ
Input current noise	$f = 10\text{ MHz}$	3				pA/ $\sqrt{\text{Hz}}$	Typ

DC PERFORMANCE							
Open-loop voltage gain (A_{OL})	$V_O = \pm 50\text{ mV}$, $R_L = 499\ \Omega$	68	63	60	60	dB	Min
Input offset voltage	$V_{CM} = V_S/2$	5	10	12	12	mV	Max
Average offset voltage drift	$V_{CM} = V_S/2$			± 10	± 10	$\mu\text{V}/^\circ\text{C}$	Typ
Input bias current	$V_{CM} = V_S/2$	6	15	18	18	μA	Max
Average bias current drift	$V_{CM} = V_S/2$			± 10	± 10	nA/ $^\circ\text{C}$	Typ
Input offset current	$V_{CM} = V_S/2$	1	6	8	8	μA	Max
Average offset current drift	$V_{CM} = V_S/2$			± 10	± 10	nA/ $^\circ\text{C}$	Typ

INPUT CHARACTERISTICS							
Common-mode input range		1/4	1.3/3.7	1.4/3.6	1.5/3.5	V	Min
Common-mode rejection ratio	$V_{CM} = \pm 0.5\text{ V}$, $V_O = 2.5\text{ V}$	72	67	65	65	dB	Min
Input resistance	Common-mode	5				M Ω	Typ
Input capacitance	Common-mode / differential	0.4/0.8				pF	Typ

OUTPUT CHARACTERISTICS							
Output voltage swing	$G = +2$	1.2/3.8	1.4/3.6	1.5/3.5	1.5/3.5	V	Min
Output current (sourcing)	$R_L = 10\ \Omega$	120	100	90	90	mA	Min
Output current (sinking)	$R_L = 10\ \Omega$	65	50	40	40	mA	Min
Output impedance	$f = 1\text{ MHz}$	0.1				Ω	Typ

ELECTRICAL CHARACTERISTICS $V_S = 5\text{ V}$ (continued)

$R_F = 249\ \Omega$, $R_L = 499\ \Omega$, $G = +2$, unless otherwise noted

PARAMETER	TEST CONDITIONS	TYP	OVER TEMPERATURE				MIN/ TYP/ MAX	
		25°C	25°C	0°C to 70°C	-40°C to 85°C	UNITS		
POWER SUPPLY								
Specified operating voltage		5	15	15	15	V	Max	
Maximum quiescent current		20	22	25	27	mA	Max	
Minimum quiescent current		20	18	16	14	mA	Min	
Power supply rejection (+PSRR)	$V_{S+} = 5.5\text{ V to }4.5\text{ V}$, $V_{S-} = 0\text{ V}$	85	75	62	62	dB	Min	
Power supply rejection (-PSRR)	$V_{S+} = 5\text{ V}$, $V_{S-} = -0.5\text{ V to }0.5\text{ V}$	75	65	60	60	dB	Min	
POWER-DOWN CHARACTERISTICS (THS4275 Only)								
Power-down voltage level(1)	REF = 0 V, or V_{S-}	Enable		REF+1.8			V	Min
		Power-down		REF+1			V	Max
	REF = V_{S+} or Floating	Enable		REF-1			V	Min
		Power-down		REF-1.7			V	Max
Power-down quiescent current	PD = Ref +1.0 V, Ref = 0 V	650	800	900	1000	μA	Max	
	PD = Ref -1.7 V, Ref = V_{S+}	650	800	900	1000	μA	Max	
Turnon time delay ($t_{(ON)}$)	50% of final value	4				μs	Typ	
Turnoff time delay ($t_{(OFF)}$)	50% of final value	3				μs	Typ	
Input impedance	f = 1 MHz	6				G Ω	Typ	
Output impedance		100				k Ω	Typ	

(1) For detail information on the power-down circuit, see the powerdown section in the application information of this data sheet.

TYPICAL CHARACTERISTICS

Table of Graphs (± 5 V)

	FIGURE
Small signal unity gain frequency response	1
Small signal frequency response	2
0.1-dB gain flatness frequency response	3
Large signal frequency response	4
Slew rate vs Output voltage	5
Harmonic distortion vs Frequency	6, 7, 8, 9
Harmonic distortion vs Output voltage swing	10, 11, 12, 13
Third order intermodulation distortion vs Frequency	14, 16
Third order intercept point vs Frequency	15, 17
Voltage and current noise vs Frequency	18
Differential gain vs Number of loads	19
Differential phase vs Number of loads	20
Settling time	21
Quiescent current vs Supply voltage	22
Output voltage vs Load resistance	23
Frequency response vs Capacitive load	24
Open-loop gain and phase vs Frequency	25
Open-loop gain vs Case temperature	26
Rejection ratios vs Frequency	27
Rejection ratios vs Case temperature	28
Common-mode rejection ratio vs Input common-mode range	29
Input offset voltage vs Case temperature	30
Input bias and offset current vs Case temperature	31
Small signal transient response	32
Large signal transient response	33
Overdrive recovery	34
Closed-loop output impedance vs Frequency	35
Power-down quiescent current vs Supply voltage	36
Power-down output impedance vs Frequency	37
Turnon and turnoff delay times	38

TYPICAL CHARACTERISTICS

Table of Graphs (5 V)

	FIGURE
Small signal unity gain frequency response	39
Small signal frequency response	40
0.1-dB gain flatness frequency response	41
Large signal frequency response	42
Slew rate vs Output voltage	43
Harmonic distortion vs Frequency	44, 45, 46, 47
Harmonic distortion vs Output voltage swing	48, 49, 50, 51
Third order intermodulation distortion vs Frequency	52, 54
Third order intercept point vs Frequency	53, 55
Voltage and current noise vs Frequency	56
Settling time	57
Quiescent current vs Supply voltage	58
Output voltage vs Load resistance	59
Frequency response vs Capacitive load	60
Open-loop gain and phase vs Frequency	61
Open-loop gain vs Case temperature	62
Rejection ratios vs Frequency	63
Rejection ratios vs Case temperature	64
Common-mode rejection ratio vs Input common-mode range	65
Input offset voltage vs Case temperature	66
Input bias and offset current vs Case temperature	67
Small signal transient response	68
Large signal transient response	69
Overdrive recovery	70
Closed-loop output impedance vs Frequency	71
Power-down quiescent current vs Supply voltage	72
Power-down output impedance vs Frequency	73
Turnon and turnoff delay times	74

TYPICAL CHARACTERISTICS (± 5 V GRAPHS)

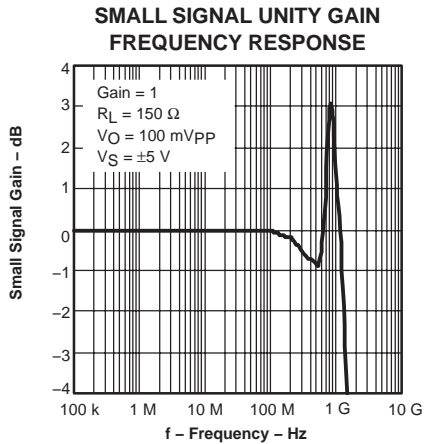


Figure 1

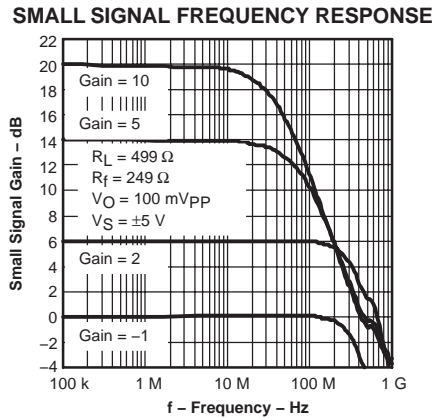


Figure 2

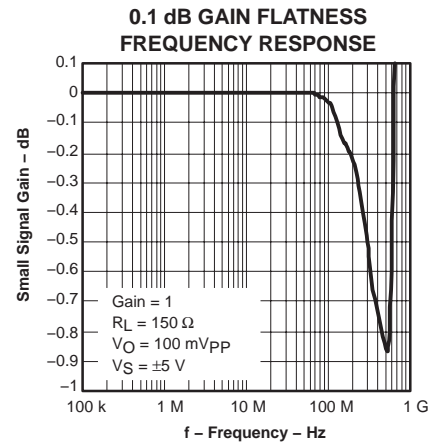


Figure 3

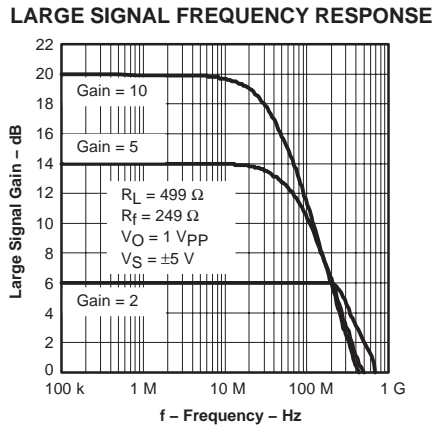


Figure 4

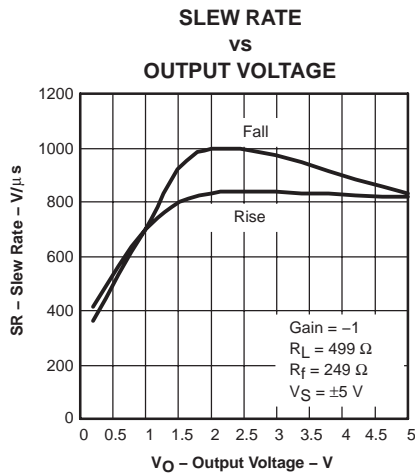


Figure 5

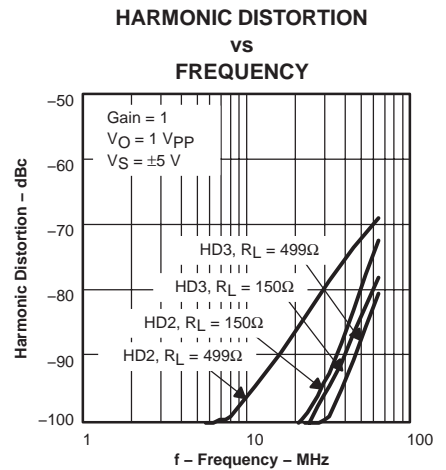


Figure 6

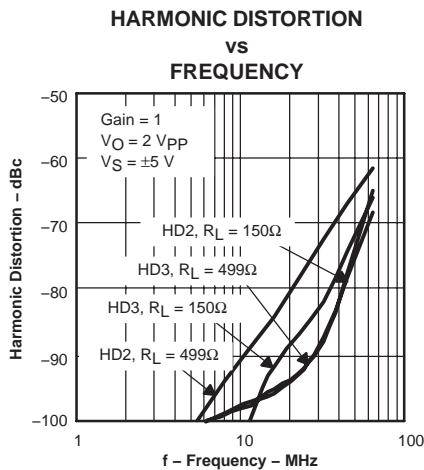


Figure 7

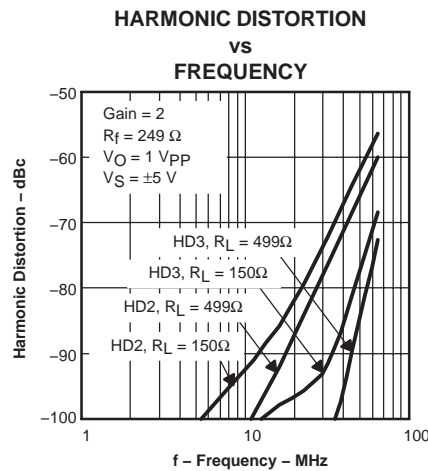


Figure 8

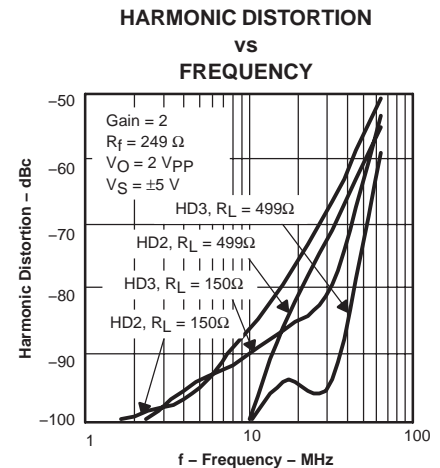


Figure 9

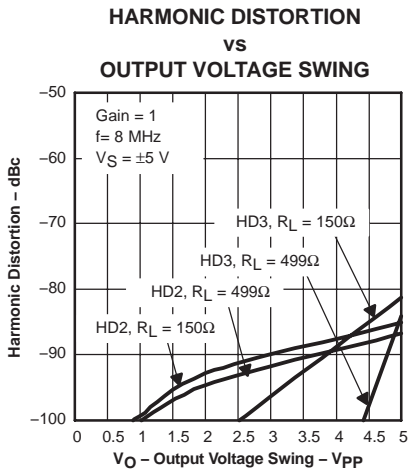


Figure 10

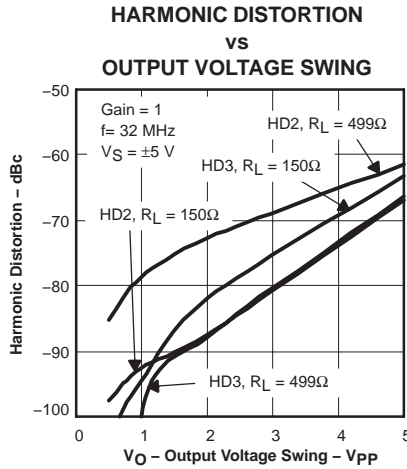


Figure 11

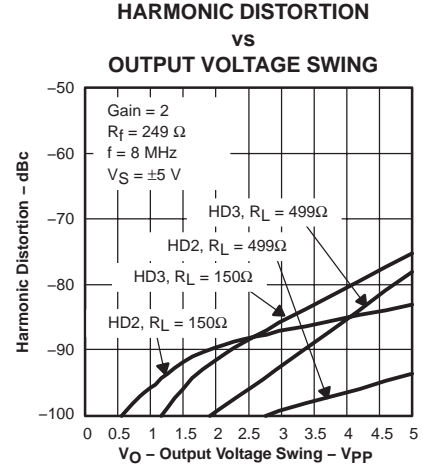


Figure 12

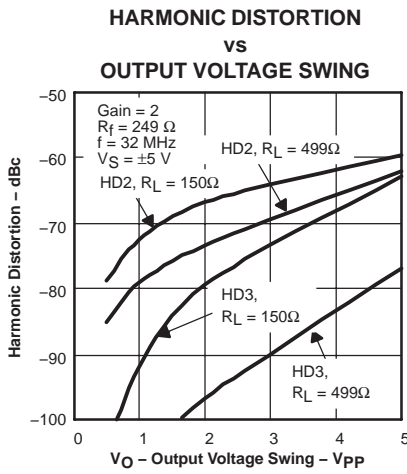


Figure 13

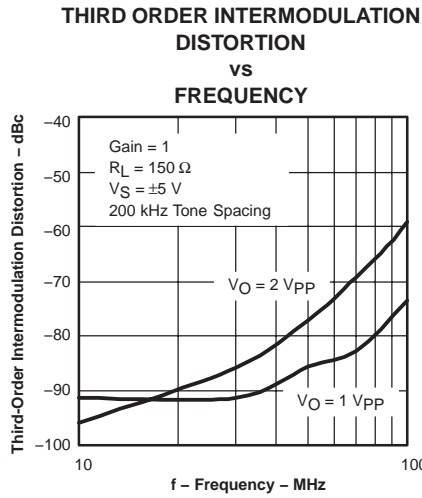


Figure 14

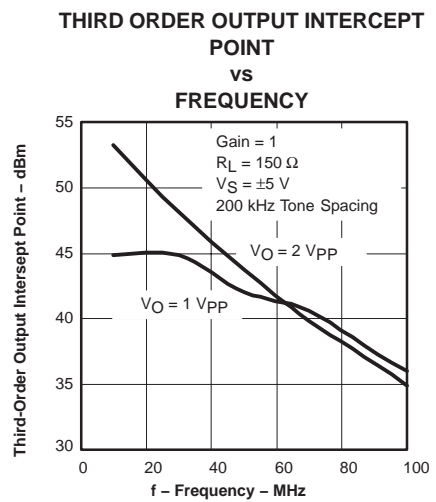


Figure 15

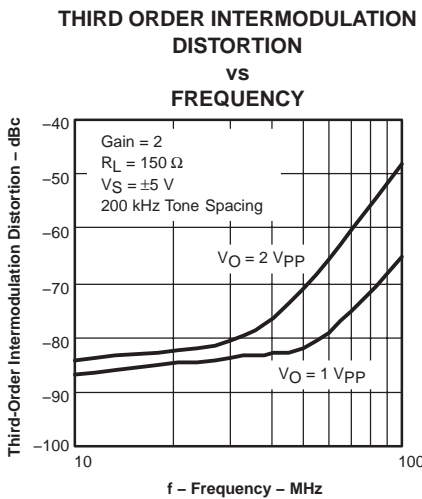


Figure 16

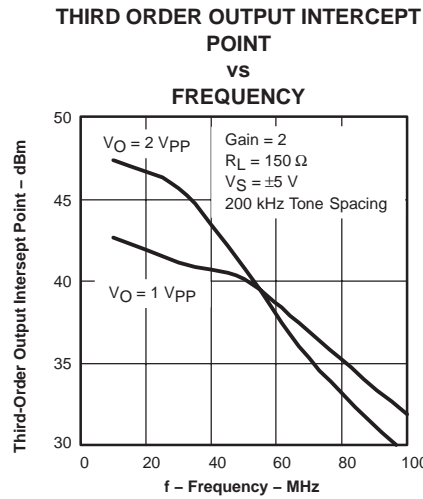


Figure 17

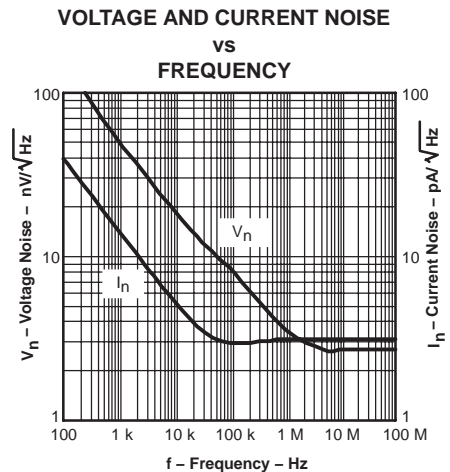


Figure 18

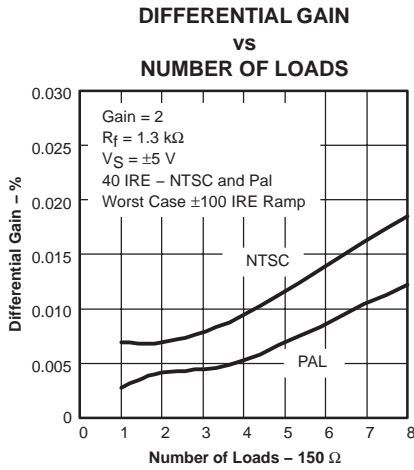


Figure 19

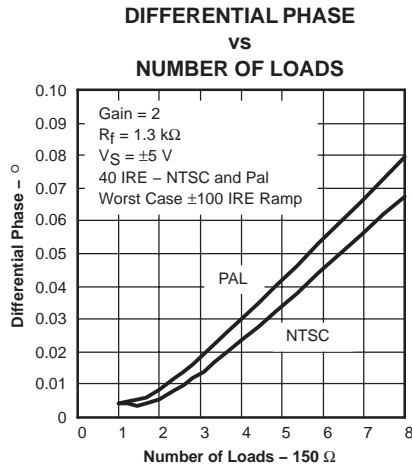


Figure 20

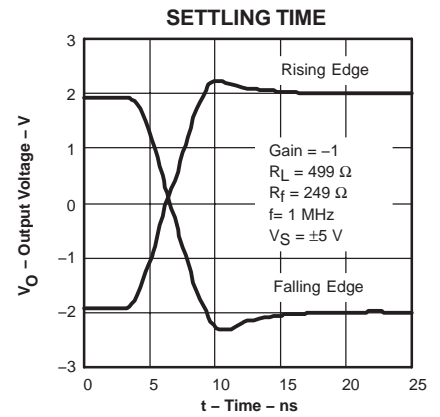


Figure 21

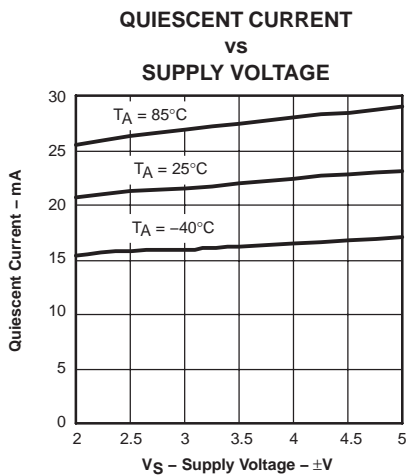


Figure 22

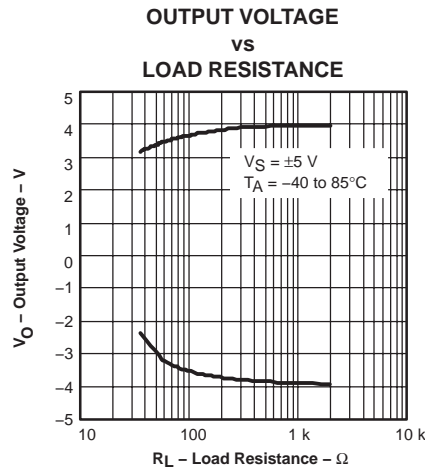


Figure 23

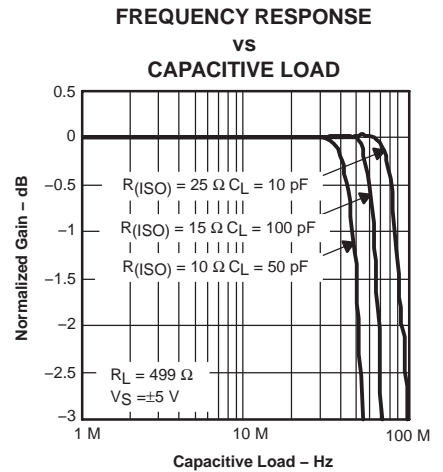


Figure 24

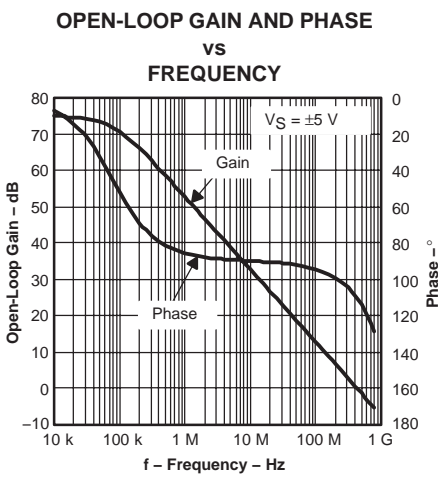


Figure 25

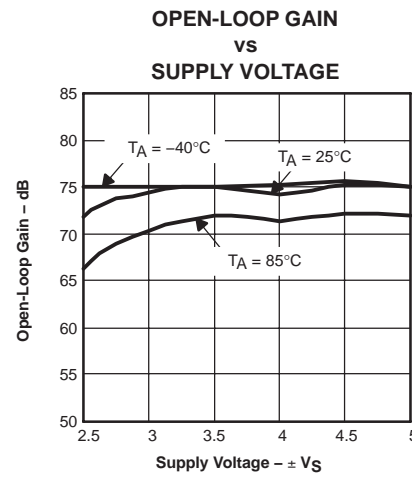


Figure 26

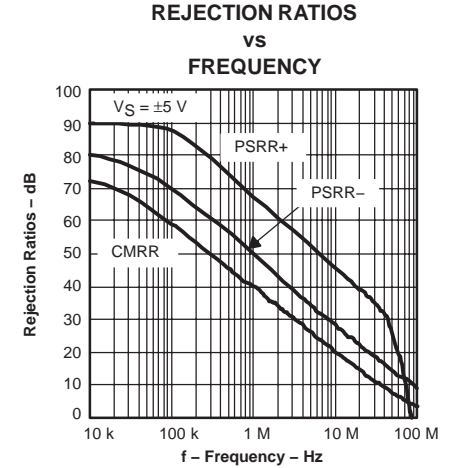


Figure 27

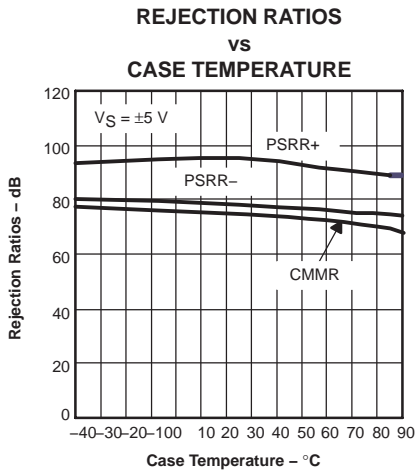


Figure 28

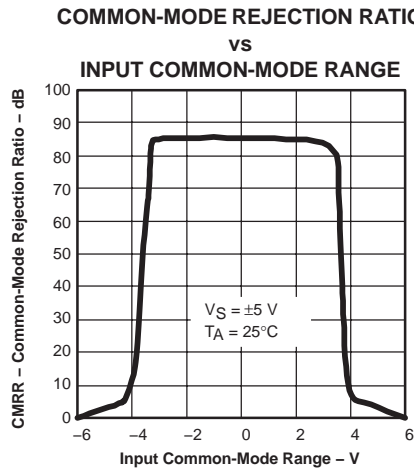


Figure 29

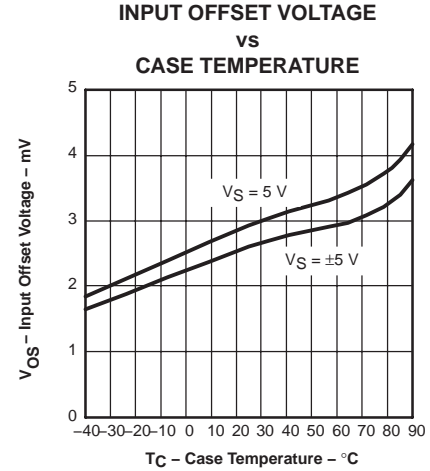


Figure 30

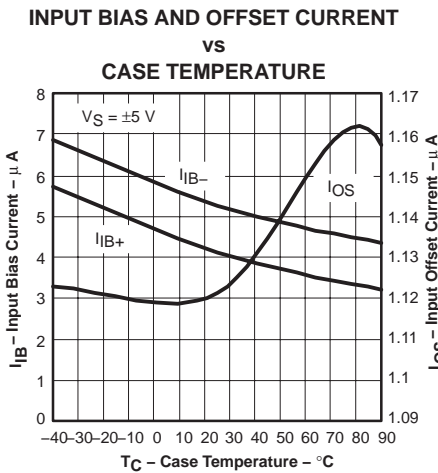


Figure 31

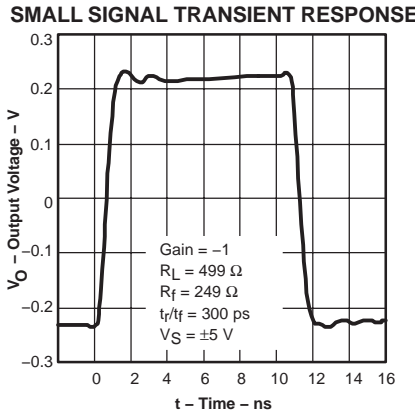


Figure 32

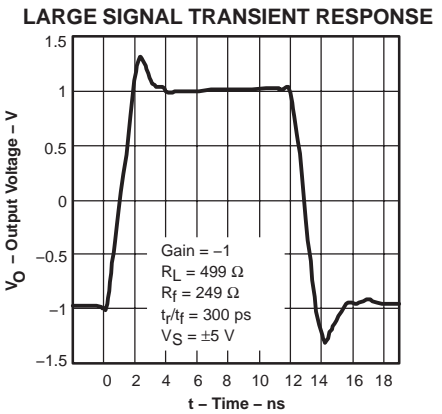


Figure 33

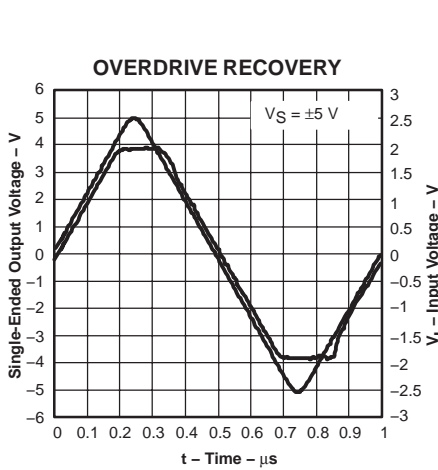


Figure 34

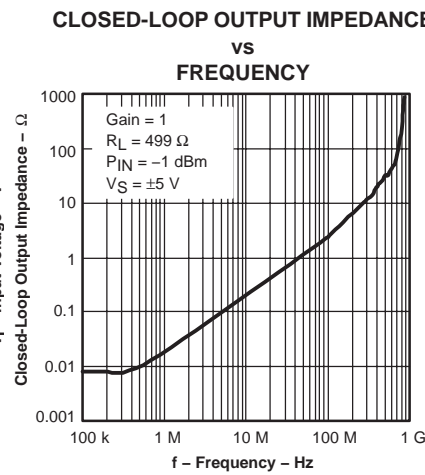


Figure 35

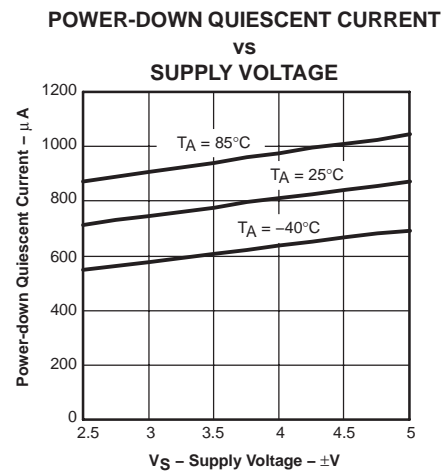


Figure 36

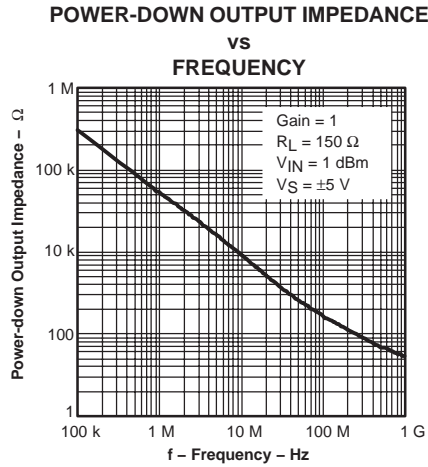


Figure 37

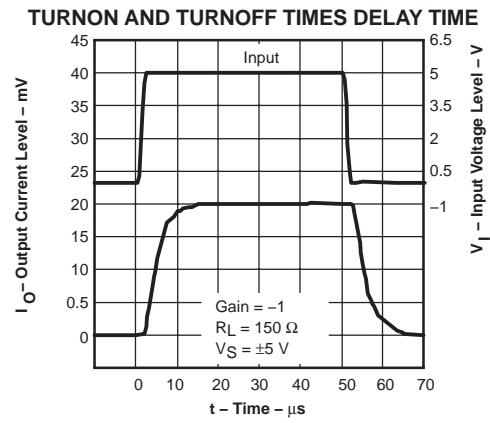


Figure 38

TYPICAL CHARACTERISTICS (5 V GRAPHS)

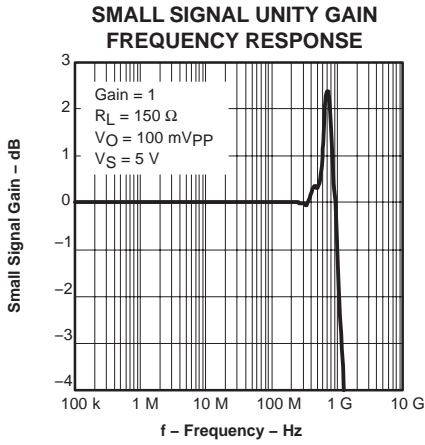


Figure 39

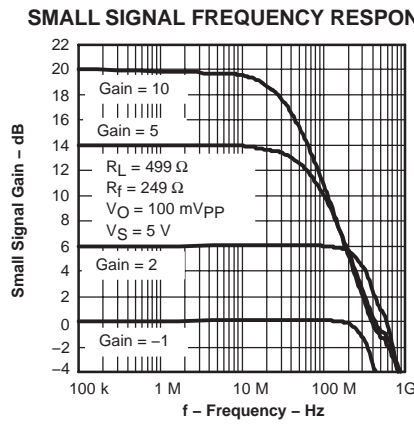


Figure 40

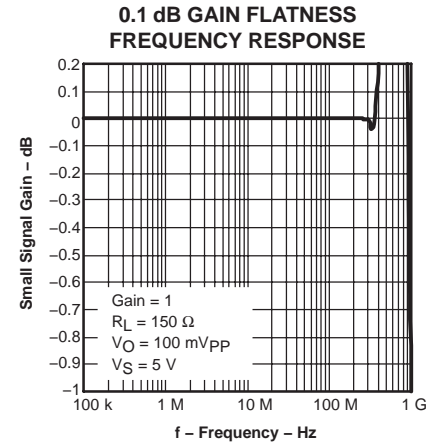


Figure 41

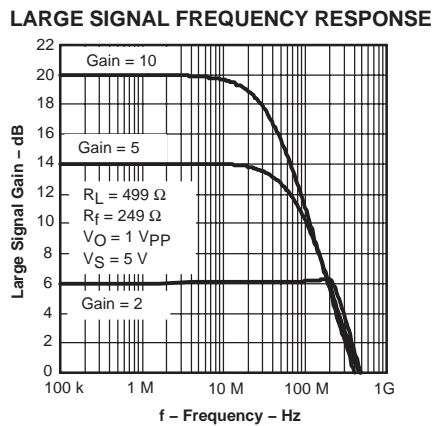


Figure 42

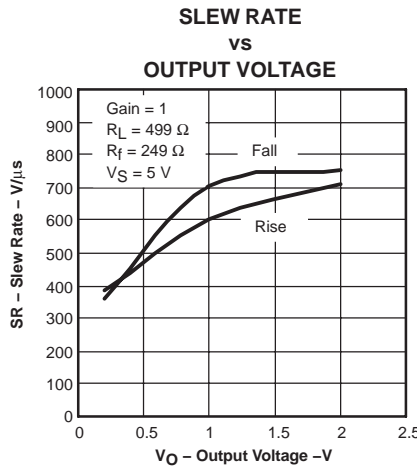


Figure 43

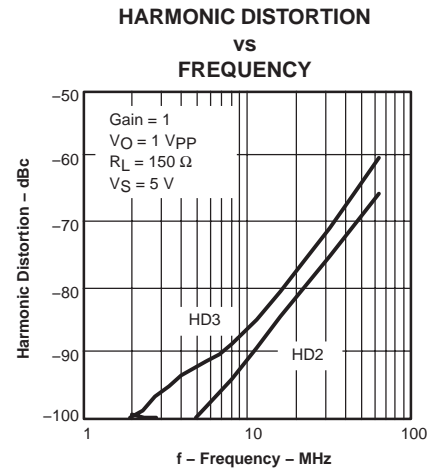


Figure 44

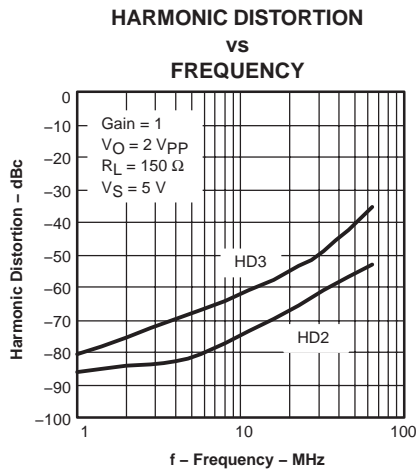


Figure 45

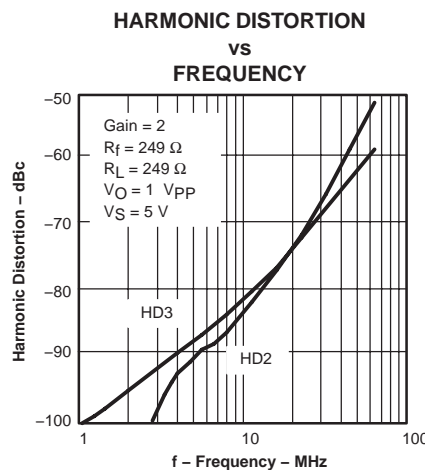


Figure 46

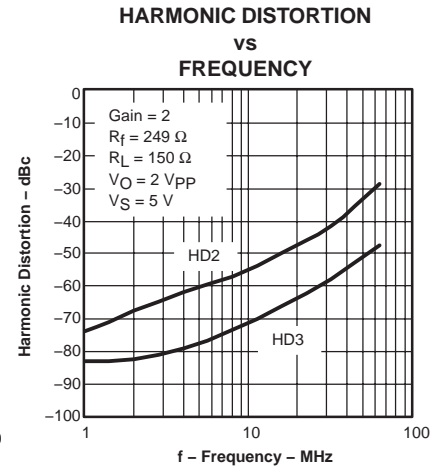


Figure 47

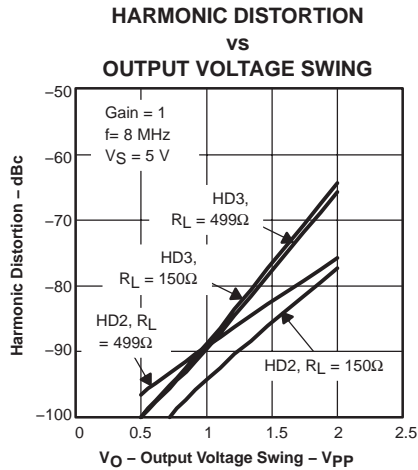


Figure 48

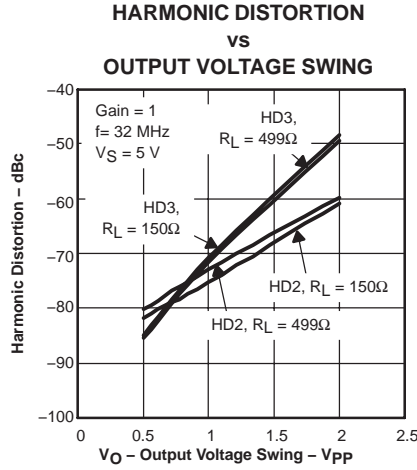


Figure 49

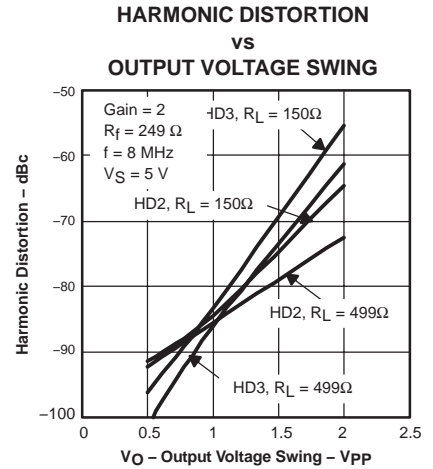


Figure 50

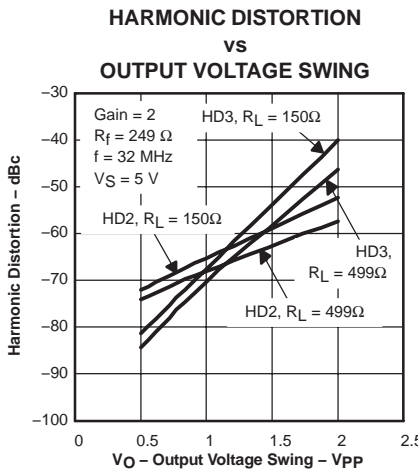


Figure 51

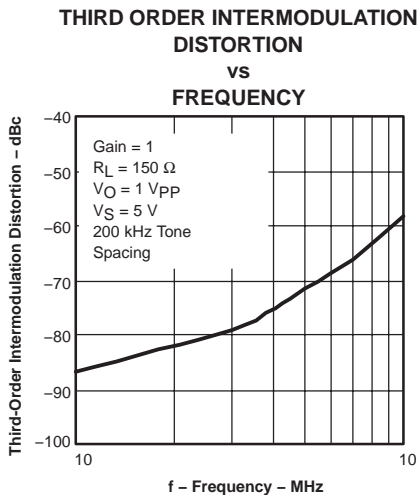


Figure 52

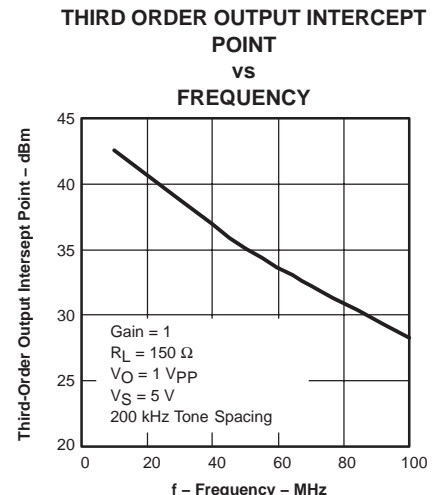


Figure 53

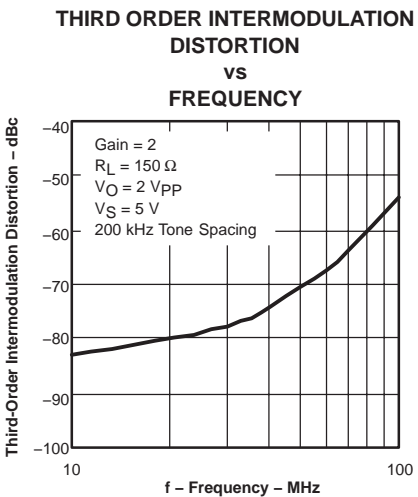


Figure 54

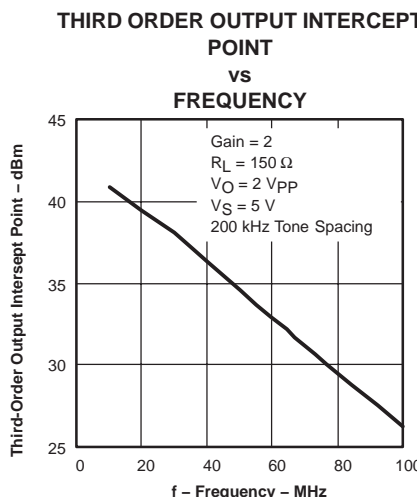


Figure 55

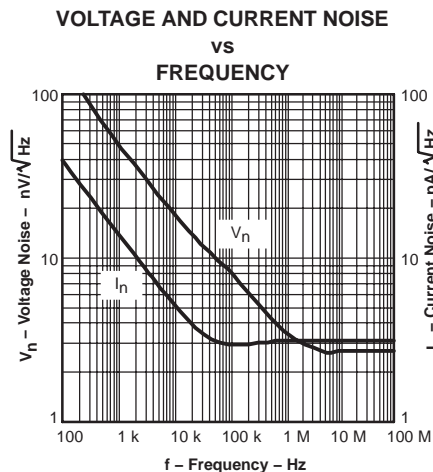


Figure 56

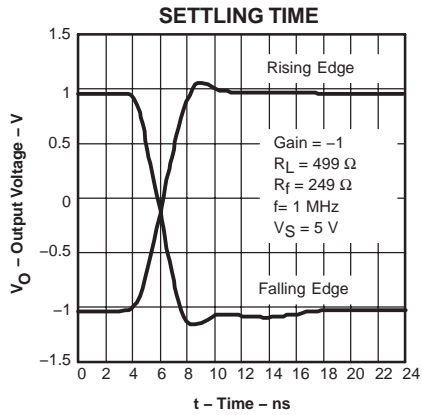


Figure 57

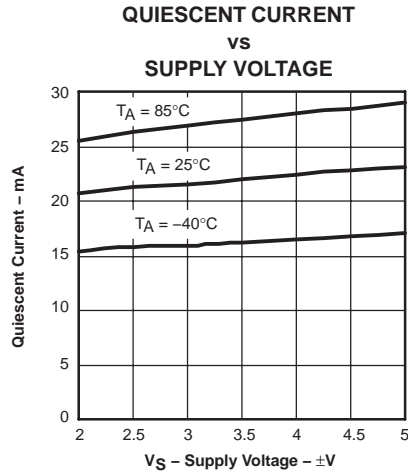


Figure 58

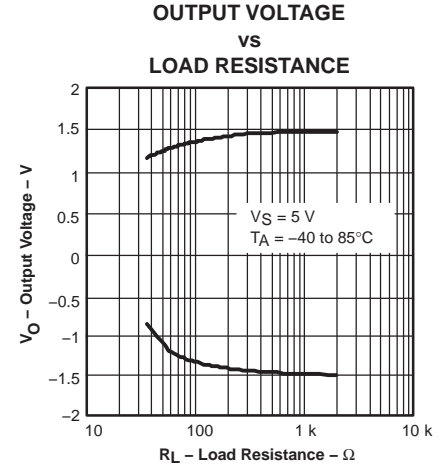


Figure 59

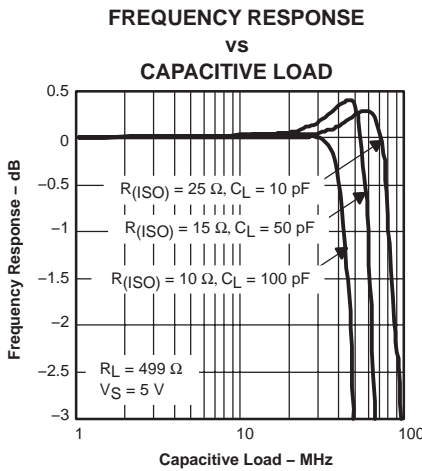


Figure 60

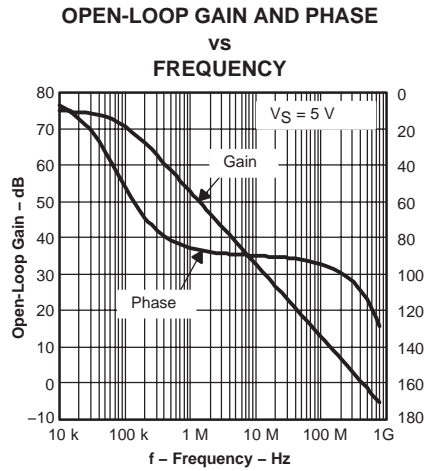


Figure 61

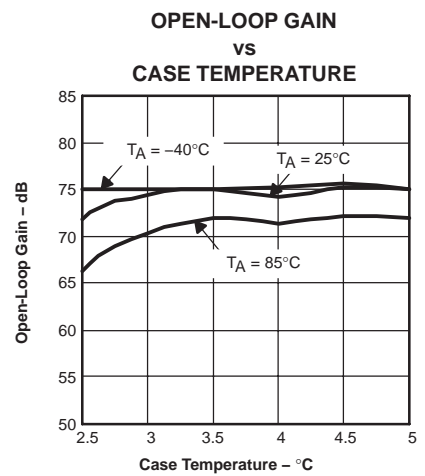


Figure 62

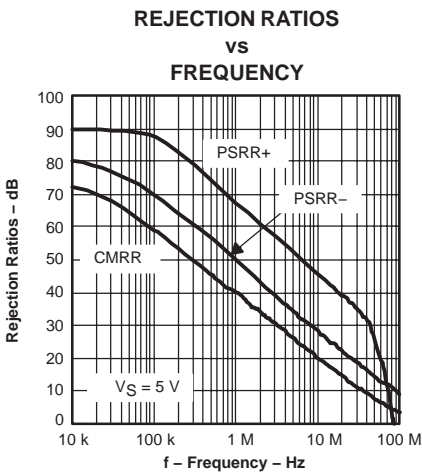


Figure 63

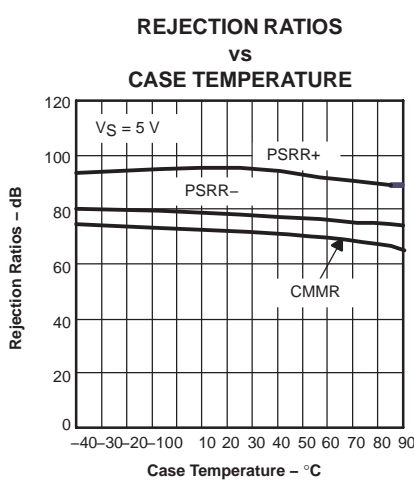


Figure 64

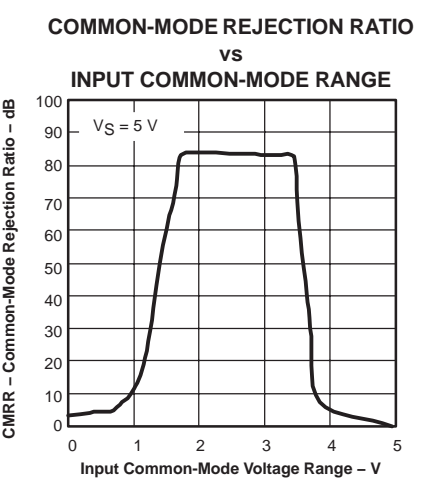


Figure 65

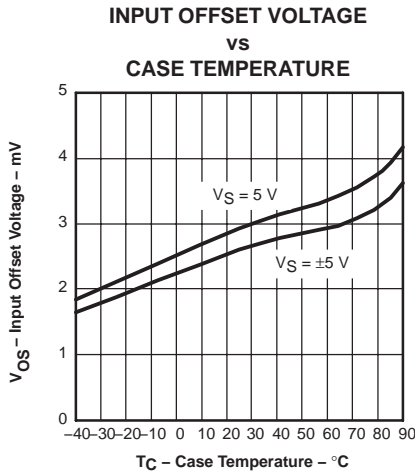


Figure 66

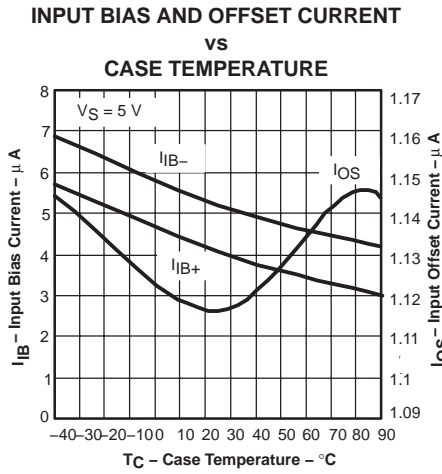


Figure 67

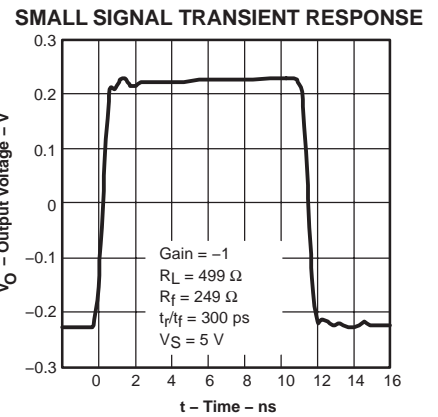


Figure 68

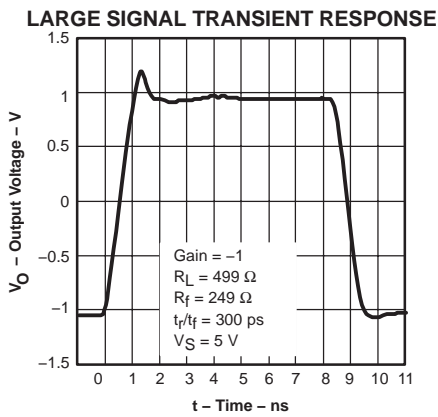


Figure 69

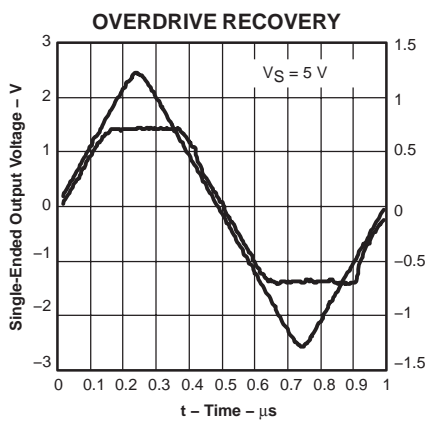


Figure 70

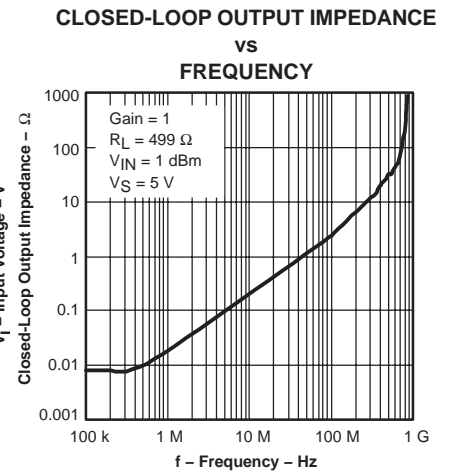


Figure 71

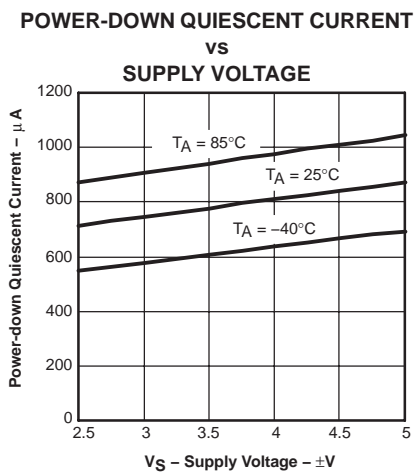


Figure 72

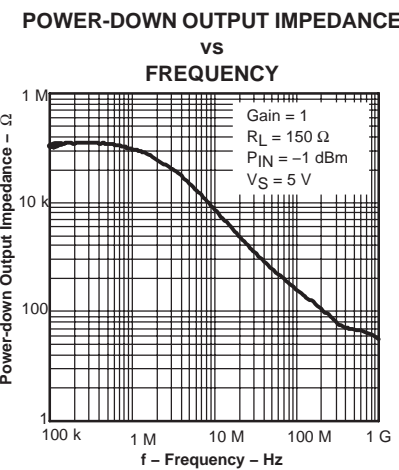


Figure 73

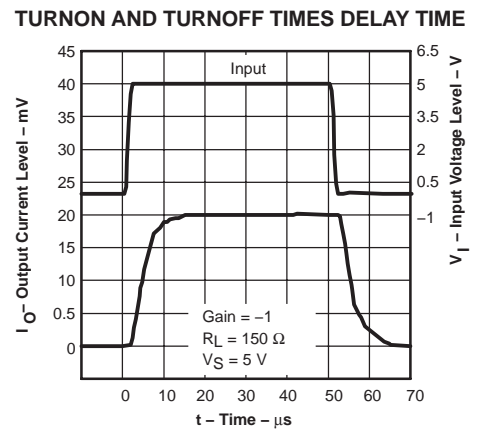


Figure 74

APPLICATION INFORMATION

HIGH-SPEED OPERATIONAL AMPLIFIERS

The THS4271 and the THS4275 operational amplifiers set new performance levels, combining low distortion, high slew rates, low noise, and a unity-gain bandwidth in excess of 1 GHz. To achieve the full performance of the amplifier, careful attention must be paid to printed-circuit board layout and component selection.

The THS4275 provides a power-down mode, providing the ability to save power when the amplifier is inactive. A reference pin is provided to allow the user the flexibility to control the threshold levels of the power-down control pin.

Applications Section Contents

- Wideband, Noninverting Operation
- Wideband, Inverting Gain Operation
- Single Supply Operation
- Saving Power With Power-Down Functionality and Setting Threshold Levels With the Reference Pin
- Power Supply Decoupling Techniques and Recommendations
- Using the THS4271 as a DAC Output Buffer
- Driving an ADC With the THS4271
- Active Filtering With the THS4271
- Building a Low-Noise Receiver With the THS4271
- Linearity: Definitions, Terminology, Circuit Techniques and Design Tradeoffs
- An Abbreviated Analysis of Noise in Amplifiers
- Driving Capacitive Loads
- Printed Circuit Board Layout Techniques for Optimal Performance
- Power Dissipation and Thermal Considerations
- Performance vs Package Options
- Evaluation Fixtures, Spice Models, and Applications Support
- Additional Reference Material
- Mechanical Package Drawings

WIDEBAND, NONINVERTING OPERATION

The THS4271 and the THS4275 are unity gain stable 1.4-GHz voltage feedback operational amplifiers, with and without power-down capability, designed to operate from a single 5-V to 15-V power supply.

Figure 75 is the noninverting gain configuration of 2 V/V used to demonstrate the typical performance curves. Most of the curves were characterized using signal sources with

50- Ω source impedance, and with measurement equipment presenting a 50- Ω load impedance. In Figure 75, the 49.9- Ω shunt resistor at the V_{IN} terminal matches the source impedance of the test generator. The total 499- Ω load at the output, combined with the 498- Ω total feedback network load, presents the THS4271 and THS4275 with an effective output load of 249 Ω for the circuit of Figure 75.

Voltage feedback amplifiers, unlike current feedback designs, can use a wide range of resistors values to set their gain with minimal impact on their stability and frequency response. Larger-valued resistors decrease the loading effect of the feedback network on the output of the amplifier, but this enhancement comes at the expense of additional noise and potentially lower bandwidth. Feedback resistor values between 249 Ω and 1 k Ω are recommended for most situations.

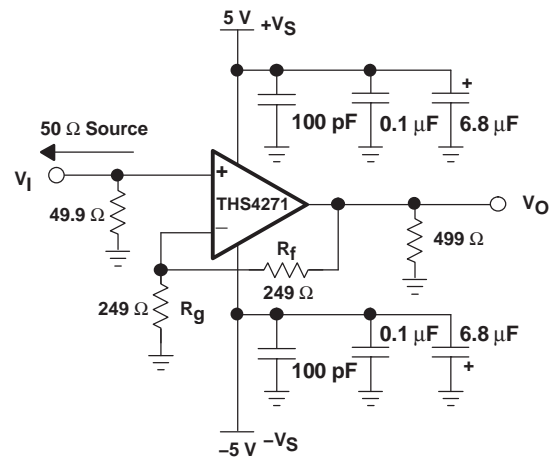


Figure 75. Wideband, Noninverting Gain Configuration

WIDEBAND, INVERTING GAIN OPERATION

Since the THS4271 and THS4275 are general-purpose, wideband voltage-feedback amplifiers, several familiar operational amplifier applications circuits are available to the designer. Figure 76 shows a typical inverting configuration where the input and output impedances and noise gain from Figure 75 are retained in an inverting circuit configuration. Inverting operation is one of the more common requirements and offers several performance benefits. The inverting configuration shows improved slew rates and distortion due to the pseudo-static voltage maintained on the inverting input.

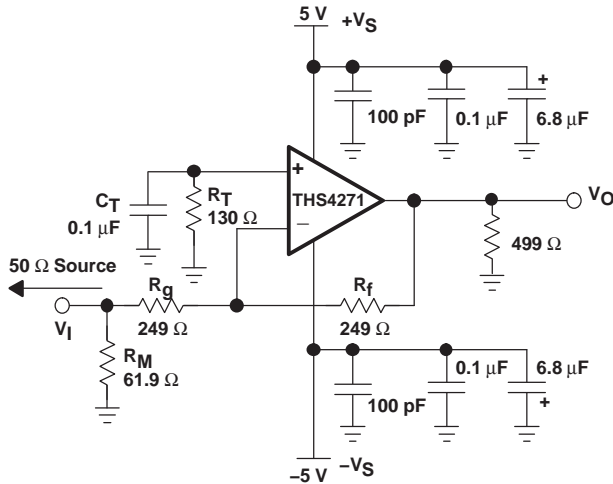


Figure 76. Wideband, Inverting Gain Configuration

In the inverting configuration, some key design considerations must be noted. One is that the gain resistor (R_g) becomes part of the signal channel input impedance. If the input impedance matching is desired (which is beneficial whenever the signal is coupled through a cable, twisted pair, long PC board trace, or other transmission line conductors), R_g may be set equal to the required termination value and R_f adjusted to give the desired gain. However, care must be taken when dealing with low inverting gains, as the resultant feedback resistor value can present a significant load to the amplifier output. For an inverting gain of 2, setting R_g to 49.9 Ω for input matching eliminates the need for R_M but requires a 100- Ω feedback resistor. This has an advantage of the noise gain becoming equal to 2 for a 50- Ω source impedance—the same as the noninverting circuit in Figure 75. However, the amplifier output now sees the 100- Ω feedback resistor in parallel with the external load. To eliminate this excessive loading, it is preferable to increase both R_g and R_f values, as shown in Figure 76, and then achieve the input matching impedance with a third resistor (R_M) to ground. The total input impedance becomes the parallel combination of R_g and R_M .

The next major consideration is that the signal source impedance becomes part of the noise gain equation and hence influences the bandwidth. For example, the R_M value combines in parallel with the external 50- Ω source impedance (at high frequencies), yielding an effective source impedance of $50 \Omega \parallel 61.9 \Omega = 27.7 \Omega$. This impedance is then added in series with R_g for calculating the noise gain. The result is 1.9 for Figure 76, as opposed to the 1.8 if R_M is eliminated. The bandwidth is lower for the gain of -2 circuit, Figure 76, ($NG=+1.9$) than for the gain of $+2$ circuit in Figure 75.

The last major consideration in inverting amplifier design is setting the bias current cancellation resistor on the noninverting input. If the resistance is set equal to the total dc resistance looking out of the inverting terminal, the output dc error, due to the input bias currents, is reduced to (input offset current) multiplied by R_f in Figure 76, the dc source impedance looking out of the inverting terminal is $249 \Omega \parallel (249 \Omega + 27.7 \Omega) = 130 \Omega$. To reduce the additional high-frequency noise introduced by the resistor at the noninverting input, and power-supply feedback, R_T is bypassed with a capacitor to ground.

SINGLE SUPPLY OPERATION

The THS4271 is designed to operate from a single 5-V to 15-V power supply. When operating from a single power supply, care must be taken to ensure the input signal and amplifier are biased appropriately to allow for the maximum output voltage swing. The circuits shown in Figure 77 demonstrate methods to configure an amplifier in a manner conducive for single supply operation.

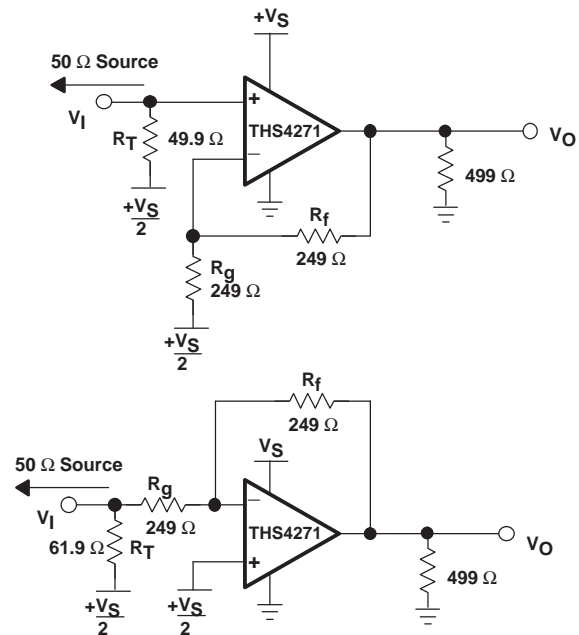


Figure 77. DC-Coupled Single Supply Operation

Saving Power With Power-Down Functionality and Setting Threshold Levels With the Reference Pin

The THS4275 features a power-down pin (\overline{PD}) which lowers the quiescent current from 22 mA down to 700 μ A, ideal for reducing system power.

The power-down pin of the amplifiers defaults to the positive supply voltage in the absence of an applied voltage, putting the amplifier in the power-on mode of operation. To turn off the amplifier in an effort to conserve power, the power-down pin can be driven towards the

negative rail. The threshold voltages for power-on and power-down are relative to the supply rails and given in the specification tables. Above the *Enable Threshold Voltage*, the device is on. Below the *Disable Threshold Voltage*, the device is off. Behavior in between these threshold voltages is not specified.

Note that this power-down functionality is just that; the amplifier consumes less power in power-down mode. The power-down mode is not intended to provide a high-impedance output. In other words, the power-down functionality is not intended to allow use as a 3-state bus driver. When in power-down mode, the impedance looking back into the output of the amplifier is dominated by the feedback and gain setting resistors, but the output impedance of the device itself varies depending on the voltage applied to the outputs.

The time delays associated with turning the device on and off are specified as the time it takes for the amplifier to reach 50% of the nominal quiescent current. The time delays are on the order of microseconds because the amplifier moves in and out of the linear mode of operation in these transitions.

Power-Down Reference Pin Operation

In addition to the power-down pin, the THS4275 also features a reference pin (REF) which allows the user to control the enable or disable power-down voltage levels applied to the $\overline{\text{PD}}$ pin. Operation of the reference pin as it relates to the power-down pin is described below.

In most split-supply applications, the reference pin is connected to ground. In some cases, the user may want to connect it to the negative or positive supply rail. In either case, the user needs to be aware of the voltage level thresholds that apply to the power-down pin. The tables below show examples and illustrate the relationship between the reference voltage and the power-down thresholds.

POWER-DOWN THRESHOLD VOLTAGE LEVELS (REF ≤ MIDRAIL)			
SUPPLY VOLTAGE (V)	REFERENCE PIN VOLTAGE (V)	ENABLE LEVEL (V)	DISABLE LEVEL (V)
±5	GND	≥ 1.8	≤ 1
	-2.5	≥ -0.7	≤ -1.5
	-5	≥ -3.2	≤ -4
5	GND	≥ 1.8	≤ 1
	1	≥ 2.8	≤ 2
	2.5	≥ 4.3	≤ 3.5

In the above table, the threshold levels are derived by the following equations:
 REF + 1.8 V for enable
 REF + 1 V for disable

Note that in order to maintain these threshold levels, the reference pin can be any voltage between V_{s-} or GND up to $V_s/2$ (midrail).

POWER-DOWN THRESHOLD VOLTAGE LEVELS (REF > MIDRAIL)			
SUPPLY VOLTAGE (V)	REFERENCE PIN VOLTAGE (V)	ENABLE LEVEL (V)	DISABLE LEVEL (V)
±5	Floating or 5	≥ 4	≤ 3.3
	2.5	≥ 1.5	≤ 0.8
	1	≥ 0	≤ -0.7
5	Floating or 5	≥ 3.3	≤ 3.3
	4	≥ 3	≤ 2.3
	3.5	≥ 2.5	≤ 1.8

In the above table, the threshold levels are derived by the following equations:

REF – 1 V for enable
 REF – 1.7 V for disable

Note that in order to maintain these threshold levels, the reference pin can be any voltage between $(V_{s+}/2) + 1$ V to V_{s+} .

The recommended mode of operation is to tie the reference pin to midrail, thus setting the threshold levels to midrail +1 V and midrail +1.8 V.

NO. OF CHANNELS	PACKAGES
Single (8-pin)	THS4275D, THS4275DGN, and THS4275DRB

Power Supply Decoupling Techniques and Recommendations

Power supply decoupling is a critical aspect of any high-performance amplifier design process. Careful decoupling provides higher quality ac performance (most notably improved distortion performance). The following guidelines ensure the highest level of performance.

1. Place decoupling capacitors as close to the power supply inputs as possible, with the goal of minimizing the inductance of the path from ground to the power supply.
2. Placement priority should put the smallest valued capacitors closest to the device.
3. Use of solid power and ground planes is recommended to reduce the inductance along power supply return current paths, with the exception of the areas underneath the input and output pins.
4. Recommended values for power supply decoupling include a bulk decoupling capacitor (6.8 to 22 μF), a mid-range decoupling capacitor (0.1 μF) and a high frequency decoupling capacitor (1000 pF) for each supply. A 100-pF capacitor can be used across the supplies as well for extremely high frequency return currents, but often is not required.

APPLICATION CIRCUITS

Driving an Analog-to-Digital Converter With the THS4271

The THS4271 can be used to drive high-performance analog-to-digital converters. Two example circuits are presented below.

The first circuit uses a wideband transformer to convert a single-ended input signal into a differential signal. The differential signal is then amplified and filtered by two THS4271 amplifiers. This circuit provides low intermodulation distortion, suppressed even-order distortion, 14 dB of voltage gain, a 50- Ω input impedance, and a single-pole filter at 100 MHz. For applications without signal content at dc, this method of driving ADCs can be very useful. Where dc information content is required, the THS4500 family of fully differential amplifiers may be applicable.

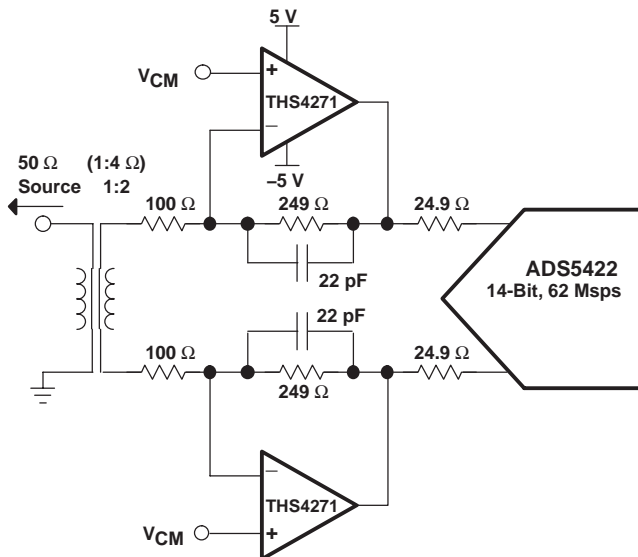
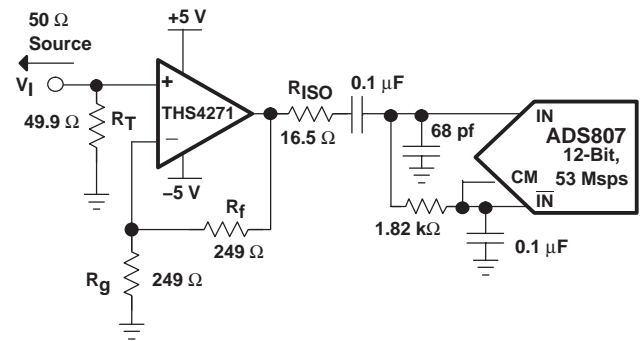


Figure 78. A Linear, Low Noise, High Gain ADC Preamplifier

The second circuit depicts single-ended ADC drive. While not recommended for optimum performance using converters with differential inputs, satisfactory performance can sometimes be achieved with single-ended input drive. An example circuit is shown here for reference.



NOTE: For best performance, high-speed ADCs should be driven differentially. See the THS4500 family of devices for more information.

Figure 79. Driving an ADC With a Single-Ended Input

Using the THS4271 as a DAC Output Buffer

Two example circuits are presented here showing the THS4271 buffering the output of a digital-to-analog converter. The first circuit performs a differential to single-ended conversion with the THS4271 configured as a difference amplifier. The difference amplifier can double as the termination mechanism for the DAC outputs as well.

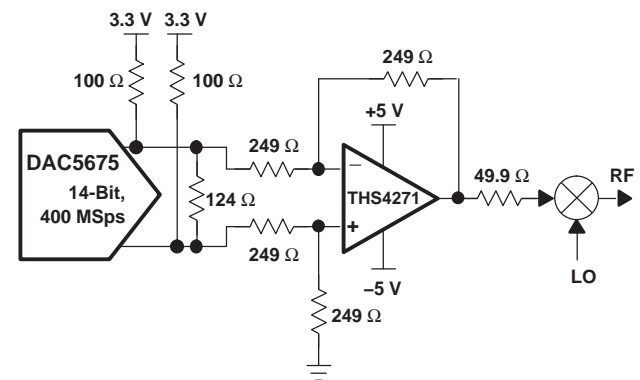


Figure 80. Differential to Single-Ended Conversion of a High-Speed DAC Output

For cases where a differential signaling path is desirable, a pair of THS4271 amplifiers can be used as output buffers. The circuit depicts differential drive into a mixer's IF inputs, coupled with additional signal gain and filtering.

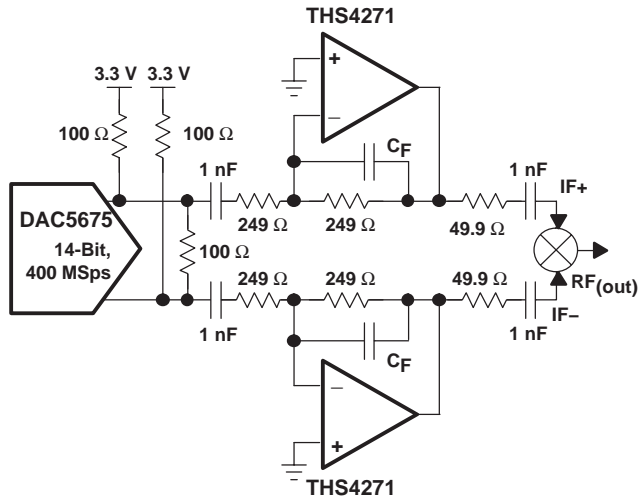


Figure 81. Differential Mixer Drive Circuit Using the DAC5675 and the THS4271

Active Filtering With the THS4271

High-frequency active filtering with the THS4271 is achievable due to the amplifier's high slew-rate, wide bandwidth, and voltage feedback architecture. Several options are available for high-pass, low-pass, bandpass, and bandstop filters of varying orders. A simple two-pole low pass filter is presented here as an example, with two poles at 100 MHz.

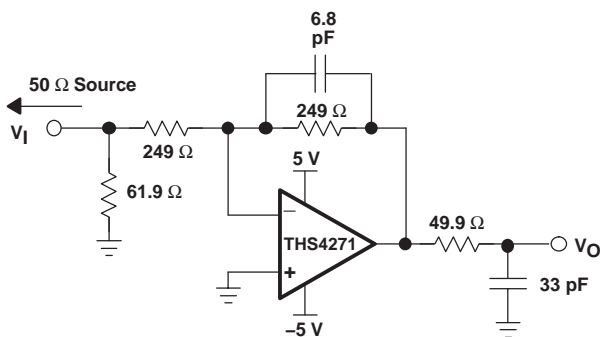


Figure 82. A Two-Pole Active Filter With Two Poles Between 90 MHz and 100 MHz

A Low-Noise Receiver With the THS4271

A combination of two THS4271 amplifiers can create a high-speed, low-distortion, low-noise differential receiver circuit as depicted in Figure 83. With both amplifiers operating in the noninverting mode of operation, the circuit presents a high load impedance to the source. The designer has the option of controlling the impedance through termination resistors if a matched termination impedance is desired.

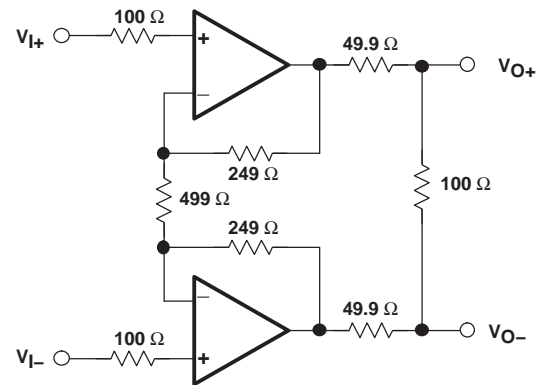


Figure 83. A High Input Impedance, Low Noise, Differential Receiver

A modification on this circuit to include a difference amplifier turns this circuit into a high-speed instrumentation amplifier, as shown in Figure 84.

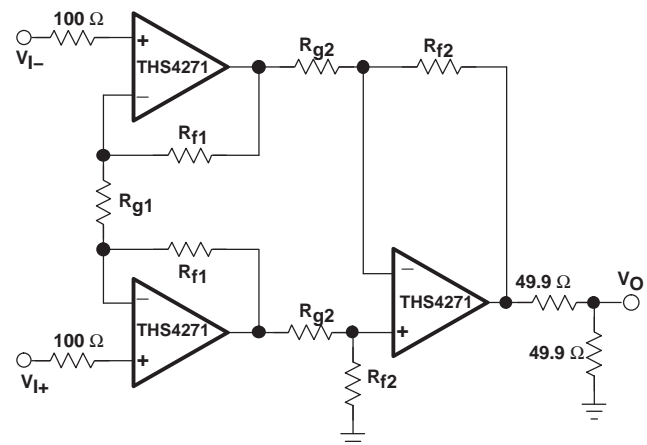


Figure 84. A High-Speed Instrumentation Amplifier

$$V_o = \frac{1}{2} \left(1 + \frac{2R_{f1}}{R_{g1}} \right) (V_{i+} - V_{i-}) \left(\frac{R_{f2}}{R_{g2}} \right) \quad (1)$$

THEORY AND GUIDELINES

Distortion Performance

The THS4271 provides excellent distortion performance into a 150-ohm load. Relative to alternative solutions, it provides exceptional performance into lighter loads, as well as exceptional performance on a single 5-V supply. Generally, until the fundamental signal reaches very high frequency or power levels, the 2nd harmonic dominates the total harmonic distortion with a negligible 3rd harmonic component. Focusing then on the 2nd harmonic, increasing the load impedance improves distortion

directly. The total load includes the feedback network; in the noninverting configuration (Figure 75) this is the sum of R_f and R_g , while in the inverting configuration (Figure 76), only R_f needs to be included in parallel with the actual load.

LINEARITY: DEFINITIONS, TERMINOLOGY, CIRCUIT TECHNIQUES, AND DESIGN TRADEOFFS

The THS4271 features excellent distortion performance for monolithic operational amplifiers. This section focuses on the fundamentals of distortion, circuit techniques for reducing nonlinearity, and methods for equating distortion of operational amplifiers to desired linearity specifications in RF receiver chains.

Amplifiers are generally thought of as *linear* devices. The output of an amplifier is a linearly scaled version of the input signal applied to it. However, amplifier transfer functions are nonlinear. Minimizing amplifier nonlinearity is a primary design goal in many applications.

Intercept points are specifications long used as key design criteria in the RF communications world as a metric for the intermodulation distortion performance of a device in the signal chain (e.g., amplifiers, mixers, etc.). Use of the intercept point, rather than strictly the intermodulation distortion, allows simpler system-level calculations. Intercept points, like noise figures, can be easily cascaded back and forth through a signal chain to determine the overall receiver chain's intermodulation distortion performance. The relationship between intermodulation distortion and intercept point is depicted in Figure 85 and Figure 86.

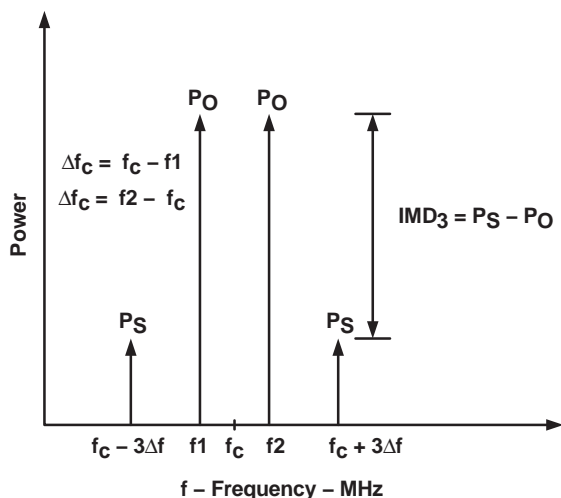


Figure 85

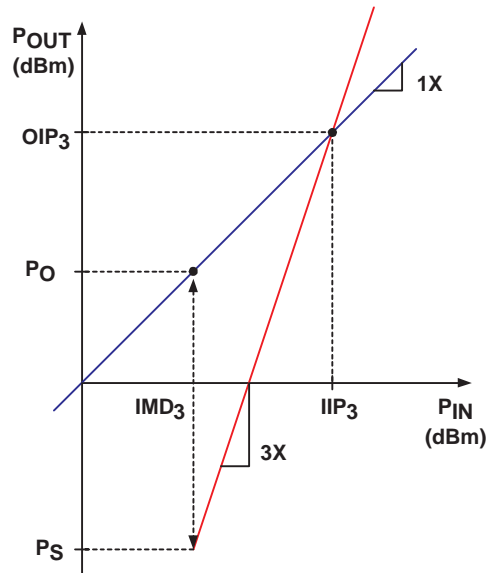


Figure 86

Due to the intercept point's ease of use in system level calculations for receiver chains, it has become the specification of choice for guiding distortion-related design decisions. Traditionally, these systems use primarily class-A, single-ended RF amplifiers as gain blocks. These RF amplifiers are typically designed to operate in a 50- Ω environment. Giving intercept points in dBm, implies an associated impedance (50 Ω).

However, with an operational amplifier, the output does not require termination as an RF amplifier would. Because closed-loop amplifiers deliver signals to their outputs regardless of the impedance present, it is important to comprehend this when evaluating the intercept point of an operational amplifier. The THS4271 yields optimum distortion performance when loaded with 150 Ω to 1 k Ω , very similar to the input impedance of an analog-to-digital converter over its input frequency band.

As a result, terminating the input of the ADC to 50 Ω can actually be detrimental to systems performance.

The discontinuity between open-loop, class-A amplifiers and closed-loop, class-AB amplifiers becomes apparent when comparing the intercept points of the two types of devices. Equations 1 and 2 gives the definition of an intercept point, relative to the intermodulation distortion.

$$OIP_3 = P_O + \left(\frac{|IMD_3|}{2} \right) \text{ where} \quad (2)$$

$$P_O = 10 \log \left(\frac{V_P^2}{2R_L \times 0.001} \right) \quad (3)$$

NOTE: P_O is the output power of a single tone, R_L is the load resistance, and V_P is the peak voltage for a single tone.

NOISE ANALYSIS

High slew rate, unity gain stable, voltage-feedback operational amplifiers usually achieve their slew rate at the expense of a higher input noise voltage. The 3 nV/√Hz input voltage noise for the THS4271 and THS4275 is, however, much lower than comparable amplifiers. The input-referred voltage noise, and the two input-referred current noise terms (3 pA/√Hz), combine to give low output noise under a wide variety of operating conditions. Figure 87 shows the amplifier noise analysis model with all the noise terms included. In this model, all noise terms are taken to be noise voltage or current density terms in either nV/√Hz or pA/√Hz.

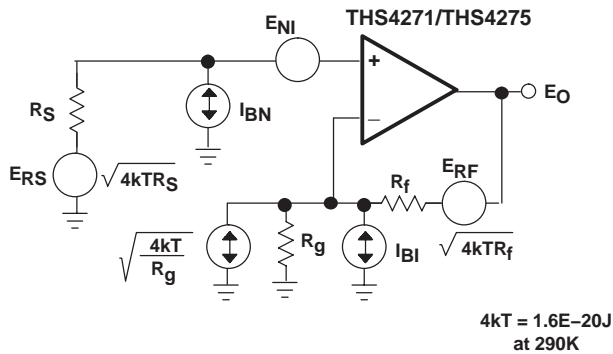


Figure 87. Noise Analysis Model

The total output shot noise voltage can be computed as the square of all square output noise voltage contributors. Equation 3 shows the general form for the output noise voltage using the terms shown in Figure 87:

$$E_O = \sqrt{\left(E_{NI}^2 + (I_{BN}R_S)^2 + 4kTR_S\right)NG^2 + (I_{BI}R_f)^2 + 4kTR_f} \quad (4)$$

Dividing this expression by the noise gain ($NG=(1+R_f/R_g)$) gives the equivalent input-referred spot noise voltage at the noninverting input, as shown in Equation 4:

$$E_O = \sqrt{E_{NI}^2 + (I_{BN}R_S)^2 + 4kTR_S + \left(\frac{I_{BI}R_f}{NG}\right)^2 + \frac{4kTR_f}{NG}} \quad (5)$$

Evaluation of these two equations for the circuit and component values shown in Figure 75 will give a total output spot noise voltage of 12.2 nV/√Hz and a total equivalent input spot noise voltage of 6.2 nV/√Hz. This includes the noise added by the resistors. This total input-referred spot noise voltage is not much higher than the 3 nV/√Hz specification for the amplifier voltage noise alone.

Driving Capacitive Loads

One of the most demanding, and yet very common, load conditions for an op amp is capacitive loading. Often, the capacitive load is the input of an A/D converter, including additional external capacitance, which may be recommended to improve A/D linearity. A high-speed, high open-loop gain amplifier like the THS4271 can be very susceptible to decreased stability and closed-loop response peaking when a capacitive load is placed directly on the output pin. When the amplifier's open-loop output resistance is considered, this capacitive load introduces an additional pole in the signal path that can decrease the phase margin. When the primary considerations are frequency response flatness, pulse response fidelity, or distortion, the simplest and most effective solution is to isolate the capacitive load from the feedback loop by inserting a series isolation resistor between the amplifier output and the capacitive load. This does not eliminate the pole from the loop response, but rather shifts it and adds a zero at a higher frequency. The additional zero acts to cancel the phase lag from the capacitive load pole, thus increasing the phase margin and improving stability.

The *Typical Characteristics* show the recommended isolation resistor vs capacitive load and the resulting frequency response at the load. Parasitic capacitive loads greater than 2 pF can begin to degrade the performance of the THS4271. Long PC board traces, unmatched cables, and connections to multiple devices can easily cause this value to be exceeded. Always consider this effect carefully, and add the recommended series resistor as close as possible to the THS4271 output pin (see Board Layout Guidelines).

The criterion for setting this $R_{(ISO)}$ resistor is a maximum bandwidth, flat frequency response at the load. For a gain of +2, the frequency response at the output pin is already slightly peaked without the capacitive load, requiring relatively high values of $R_{(ISO)}$ to flatten the response at the load. Increasing the noise gain also reduces the peaking.

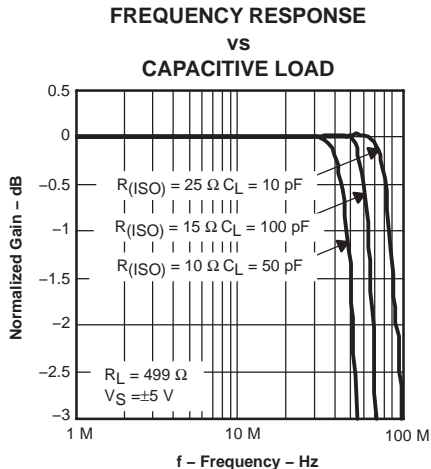


Figure 88. Isolation Resistor Diagram

BOARD LAYOUT

Achieving optimum performance with a high frequency amplifier like the THS4271 requires careful attention to board layout parasitics and external component types.

Recommendations that optimize performance include:

1. **Minimize parasitic capacitance to any ac ground for all of the signal I/O pins.** Parasitic capacitance on the output and inverting input pins can cause instability: on the noninverting input, it can react with the source impedance to cause unintentional band limiting. To reduce unwanted capacitance, a window around the signal I/O pins should be opened in all of the ground and power planes around those pins. Otherwise, ground and power planes should be unbroken elsewhere on the board.
2. **Minimize the distance (< 0.25") from the power supply pins to high frequency 0.1- μ F de-coupling capacitors.** At the device pins, the ground and power plane layout should not be in close proximity to the signal I/O pins. Avoid narrow power and ground traces to minimize inductance between the pins and the decoupling capacitors. The power supply connections should always be decoupled with these capacitors. Larger (2.2- μ F to 6.8- μ F) decoupling capacitors, effective at lower frequency, should also be used on the main supply pins. These may be placed somewhat farther from the device and may be shared among several devices in the same area of the PC board.
3. **Careful selection and placement of external components preserves the high frequency performance of the THS4271.** Resistors should be a very low reactance type. Surface-mount resistors work best and allow a tighter overall layout. Metal-film and carbon composition, axially-leaded resistors can also provide good high frequency performance.
4. **Connections to other wideband devices on the board may be made with short direct traces or through onboard transmission lines.** For short connections, consider the trace and the input to the next device as a lumped capacitive load. Relatively wide traces (50 mils to 100 mils) should be used, preferably with ground and power planes opened up around them. Estimate the total capacitive load and set R_{ISO} from the plot of recommended R_{ISO} vs capacitive load. Low parasitic capacitive loads (<4 pF) may not need an R_{ISO} , since the THS4271 is nominally compensated to operate with a 2-pF parasitic load. Higher parasitic capacitive loads without an R_{ISO} are allowed as the signal gain increases (increasing the unloaded phase margin). If a long trace is required, and the 6-dB signal loss intrinsic to a doubly-terminated transmission line is acceptable, implement a matched impedance transmission line using microstrip or stripline techniques (consult an ECL design handbook for microstrip and stripline layout techniques). A 50- Ω environment is normally not necessary onboard, and in fact, a higher impedance environment improves distortion as shown in the distortion versus load plots. With a characteristic board trace impedance defined based on board material and trace dimensions, a matching series resistor into the trace from the output of the THS4271 is used as well as a terminating shunt resistor at the input of the destination device. Remember also that the terminating impedance is the

Again, keep their leads and PC board trace length as short as possible. Never use wire-wound type resistors in a high frequency application. Since the output pin and inverting input pin are the most sensitive to parasitic capacitance, always position the feedback and series output resistor, if any, as close as possible to the output pin. Other network components, such as noninverting input-termination resistors, should also be placed close to the package. Where double-side component mounting is allowed, place the feedback resistor directly under the package on the other side of the board between the output and inverting input pins. Even with a low parasitic capacitance shunting the external resistors, excessively high resistor values can create significant time constants that can degrade performance. Good axial metal-film or surface-mount resistors have approximately 0.2 pF in shunt with the resistor. For resistor values > 2 k Ω , this parasitic capacitance can add a pole and/or a zero below 400-MHz that can effect circuit operation. Keep resistor values as low as possible, consistent with load driving considerations. A good starting point for design is to set the R_f to 249- Ω for low-gain, noninverting applications. Doing this automatically keeps the resistor noise terms low, and minimizes the effect of their parasitic capacitance.

parallel combination of the shunt resistor and the input impedance of the destination device: this total effective impedance should be set to match the trace impedance. If the 6-dB attenuation of a doubly terminated transmission line is unacceptable, a long trace can be series-terminated at the source end only. Treat the trace as a capacitive load in this case and set the series resistor value as shown in the plot of $R_{(ISO)}$ vs capacitive load. This does not preserve signal integrity or a doubly-terminated line. If the input impedance of the destination device is low, there is some signal attenuation due to the voltage divider formed by the series output into the terminating impedance.

5. **Socketing a high speed part like the THS4271 is not recommended.** The additional lead length and pin-to-pin capacitance introduced by the socket can create a troublesome parasitic network which can make it almost impossible to achieve a smooth, stable frequency response. Best results are obtained by soldering the THS4271 onto the board.

PowerPAD™ DESIGN CONSIDERATIONS

The THS4271 and THS4275 are available in a thermally-enhanced PowerPAD family of packages. These packages are constructed using a downset leadframe upon which the die is mounted [see Figure 89(a) and Figure 89(b)]. This arrangement results in the lead frame being exposed as a thermal pad on the underside of the package [see Figure 89(c)]. Because this thermal pad has direct thermal contact with the die, excellent thermal performance can be achieved by providing a good thermal path away from the thermal pad.

The PowerPAD package allows both assembly and thermal management in one manufacturing operation.

During the surface-mount solder operation (when the leads are being soldered), the thermal pad can also be soldered to a copper area underneath the package. Through the use of thermal paths within this copper area, heat can be conducted away from the package into either a ground plane or other heat dissipating device.

The PowerPAD package represents a breakthrough in combining the small area and ease of assembly of surface mount with the heretofore awkward mechanical methods of heatsinking.

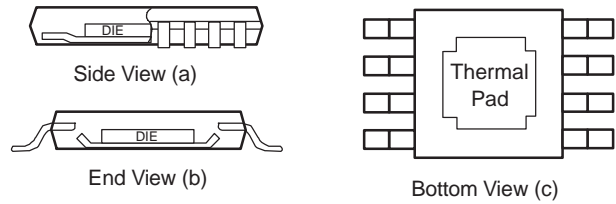


Figure 89. Views of Thermally Enhanced Package

Although there are many ways to properly heatsink the PowerPAD package, the following steps illustrate the recommended approach.

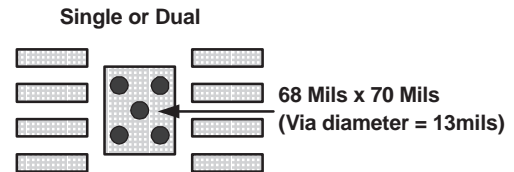


Figure 90. PowerPAD PCB Etch and Via Pattern

PowerPAD PCB LAYOUT CONSIDERATIONS

1. Prepare the PCB with a top side etch pattern as shown in Figure 90. There should be etch for the leads as well as etch for the thermal pad.
2. Place five holes in the area of the thermal pad. The holes should be 13 mils in diameter. Keep them small so that solder wicking through the holes is not a problem during reflow.
3. Additional vias may be placed anywhere along the thermal plane outside of the thermal pad area. They help dissipate the heat generated by the THS4271 and THS4275 IC. These additional vias may be larger than the 13-mil diameter vias directly under the thermal pad. They can be larger because they are not in the thermal pad area to be soldered, so that wicking is not a problem.
4. Connect all holes to the internal ground plane.
5. When connecting these holes to the ground plane, **do not** use the typical web or spoke via connection methodology. Web connections have a high thermal resistance connection that is useful for slowing the heat transfer during soldering operations. This resistance makes the soldering of vias that have plane connections easier. In this application, however, low thermal resistance is desired for the most efficient heat transfer. Therefore, the holes under the THS4271 and THS4275 PowerPAD package should make their connection to the internal ground plane, with a complete connection around the entire circumference of the plated-through hole.

- The top-side solder mask should leave the terminals of the package and the thermal pad area with its five holes exposed. The bottom-side solder mask should cover the five holes of the thermal pad area. This prevents solder from being pulled away from the thermal pad area during the reflow process.
- Apply solder paste to the exposed thermal pad area and all of the IC terminals.
- With these preparatory steps in place, the IC is simply placed in position and run through the solder reflow operation as any standard surface-mount component. This results in a part that is properly installed.

For a given θ_{JA} , the maximum power dissipation is shown in Figure 91 and is calculated by the equation 5:

$$P_D = \frac{T_{max} - T_A}{\theta_{JA}} \quad (6)$$

where:

- P_D = Maximum power dissipation of THS4271 (watts)
- T_{MAX} = Absolute maximum junction temperature (150°C)
- T_A = Free-ambient temperature (°C)
- $\theta_{JA} = \theta_{JC} + \theta_{CA}$
- θ_{JC} = Thermal coefficient from junction to the case (°C/W)
- θ_{CA} = Thermal coefficient from the case to ambient air (°C/W).

The next consideration is the package constraints. The two sources of heat within an amplifier are quiescent power and output power. The designer should never forget about the quiescent heat generated within the device, especially multi-amplifier devices. Because these devices have linear output stages (Class AB), most of the heat dissipation is at low output voltages with high output currents.

The other key factor when dealing with power dissipation is how the devices are mounted on the PCB. The PowerPAD devices are extremely useful for heat dissipation. But, the device should always be soldered to a copper plane to fully use the heat dissipation properties of the PowerPAD. The SOIC package, on the other hand, is highly dependent on how it is mounted on the PCB. As more trace and copper area is placed around the device, θ_{JA} decreases and the heat dissipation capability increases. For a single package, the sum of the RMS output currents and voltages should be used to choose the proper package.

THERMAL ANALYSIS

The THS4271 device does not incorporate automatic thermal shutoff protection, so the designer must take care to ensure that the design does not violate the absolute

maximum junction temperature of the device. Failure may result if the absolute maximum junction temperature of 150° C is exceeded.

The thermal characteristics of the device are dictated by the package and the PC board. Maximum power dissipation for a given package can be calculated using the following formula.

$$P_{Dmax} = \frac{T_{max} - T_A}{\theta_{JA}} \quad (7)$$

where:

- P_{Dmax} is the maximum power dissipation in the amplifier (W).
- T_{max} is the absolute maximum junction temperature (°C).
- T_A is the ambient temperature (°C).
- $\theta_{JA} = \theta_{JC} + \theta_{CA}$
- θ_{JC} is the thermal coefficient from the silicon junctions to the case (°C/W).
- θ_{CA} is the thermal coefficient from the case to ambient air (°C/W).

For systems where heat dissipation is more critical, the THS4271 is offered in an 8-pin MSOP with PowerPAD. The thermal coefficient for the MSOP PowerPAD package is substantially improved over the traditional SOIC. Maximum power dissipation levels are depicted in the graph for the two packages. The data for the DGN package assumes a board layout that follows the PowerPAD layout guidelines referenced above and detailed in the PowerPAD application notes in the *Additional Reference Material* section at the end of the data sheet.

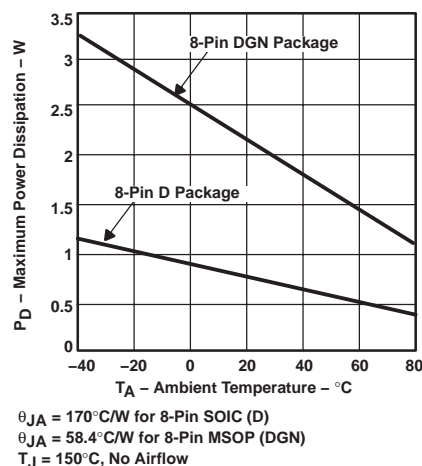


Figure 91. Maximum Power Dissipation vs Ambient Temperature

When determining whether or not the device satisfies the maximum power dissipation requirement, it is important to consider not only quiescent power dissipation, but also dynamic power dissipation. Often maximum power is difficult to quantify because the signal pattern is inconsistent, but an estimate of the RMS power dissipation can provide visibility into a possible problem.

DESIGN TOOLS

Performance vs Package Options

The THS4271 and THS4275 are offered in different package options. However, performance may be limited due to package parasitics and lead inductance in some packages. In order to achieve maximum performance of the THS4271 and THS4275, Texas Instruments recommends using the leadless MSOP (DRB) or MSOP (DGN) packages, in addition to proper high-speed PCB layout. Figure 92 shows the unity gain frequency response of the THS4271 using the leadless MSOP, MSOP, and SOIC package for comparison. Using the THS4271 and THS4275 in a unity gain with the SOIC package may result in the device becoming unstable. In higher gain configurations, this effect is mitigated by the reduced bandwidth. As such, the SOIC is suitable for application with gains equal to or higher than +2 V/V or (-1 V/V).

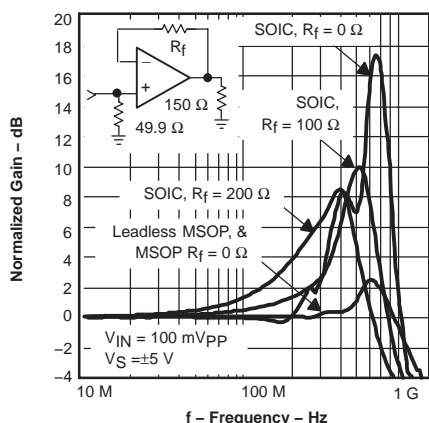


Figure 92. Effects of Unity Gain Frequency Response for Differential Packages

Evaluation Fixtures, Spice Models, and Applications Support

Texas Instruments is committed to providing its customers with the highest quality of applications support. To support this goal, evaluation boards have been developed for the THS4271 operational amplifier. Three evaluation boards are available: one THS4271 and one THS4275, both are configurable for different gains, and a third for a gain of +1 (THS4271 only). These boards are easy to use, allowing for straightforward evaluation of the device. These evaluation boards can be ordered through the Texas Instruments web site, www.ti.com, or through your local Texas Instruments sales representative. Schematics for the evaluation boards are shown below.

The THS4271/THS4275 EVM board shown in Figure 96 through Figure 99 is designed to accommodate different gain configurations. Its default component values are set to give a gain of 2. The EVM can be configured in a gain of +1; however, it is strongly not recommended. Evaluating the THS4271/THS4275 in a gain of 1 using this EVM may cause the part to become unstable. The stability of the device can be controlled by adding a large resistor in the feedback path, the performance is sacrificed. Figure 93 shows the small signal frequency response of the THS4271 with different feedback resistors in the feedback path. Figure 94 is the small frequency response of the THS4271 using the gain of 1 EVM.

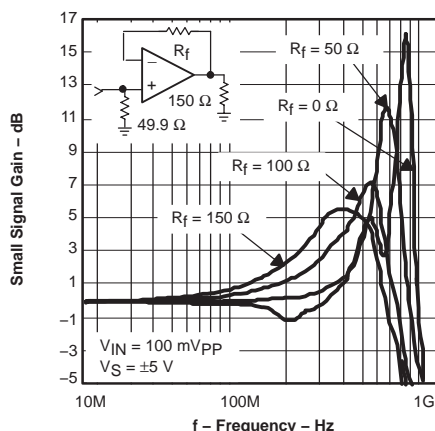


Figure 93. Frequency Response vs Feedback Resistor Using the EDGE #6439527 EVM

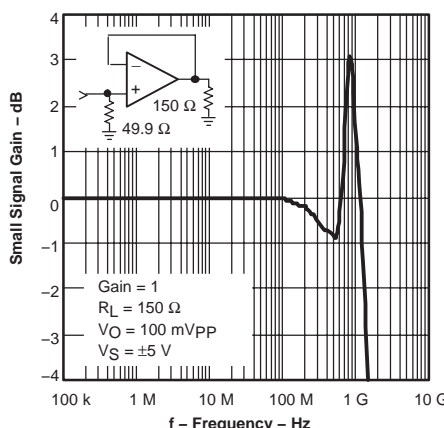


Figure 94. Frequency Response Using the EDGE # 6443547 G = +1 EVM

The peaking in the frequency response is due to the lead inductance in the feedback path. Each pad and trace on a PCB has an inductance associated with it, which in conjunction with the inductance associated with the package may cause peaking in the frequency response, causing the device to become unstable.

In order to achieve the maximum performance of the device, PCB layout is very critical. Texas Instruments has developed an EVM for the evaluation of the THS4271 in a gain of 1. The EVM is shown in Figure 101 through Figure 104. This EVM is designed to minimize peaking in the unity gain configuration.

Minimizing the inductance in the feedback path is critical for reducing the peaking of the frequency response in unity gain. The recommended maximum inductance allowed in the feedback path is 4 nH. This can be calculated by using Equation 8.

$$L(\text{nH}) = K\ell \left[\ln \frac{2\ell}{W + T} + 0.223 \frac{W + T}{\ell} + 0.5 \right] \quad (8)$$

where:

W = Width of trace in inches.

ℓ = Length of the trace in inches.

T = Thickness of the trace in inches.

K = 5.08 for dimensions in inches, and K = 2 for dimensions in cm.

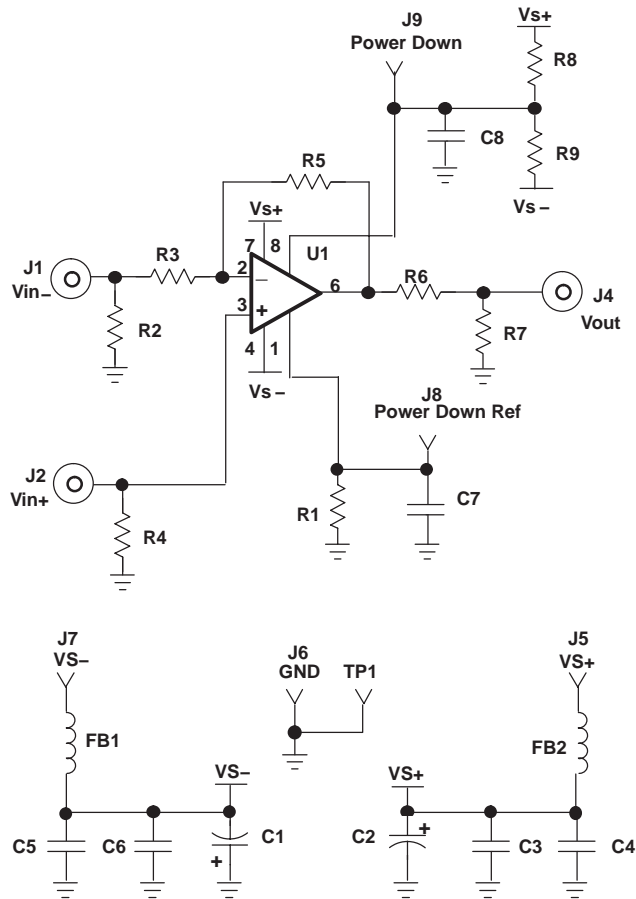


Figure 95. THS4271/THS4275 EVM Circuit Configuration

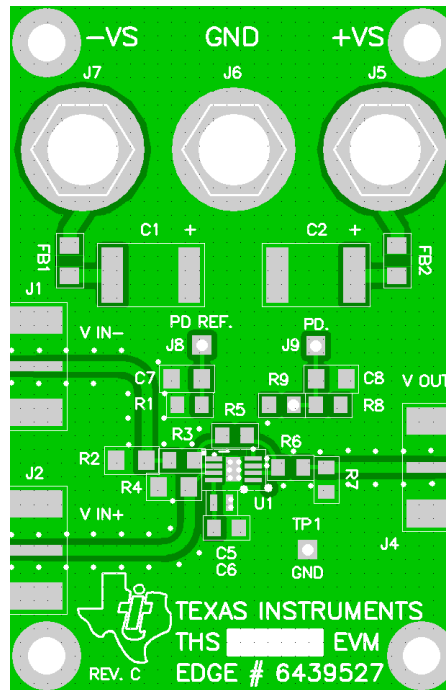


Figure 96. THS4271/THS4275 EVM Board Layout (Top Layer)

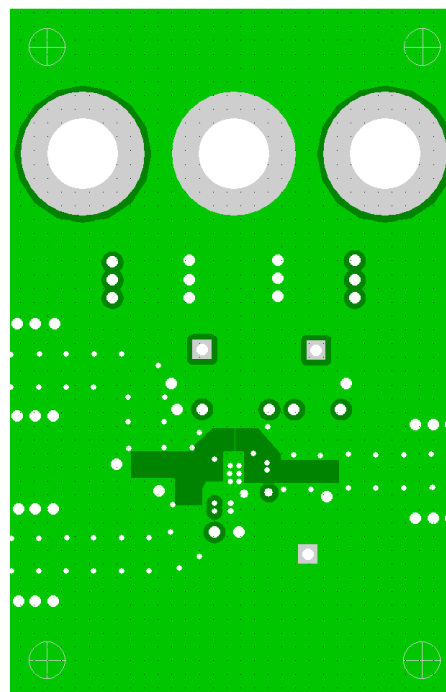


Figure 97. THS4271/THS4275 EVM Board Layout (Second Layer, Ground)

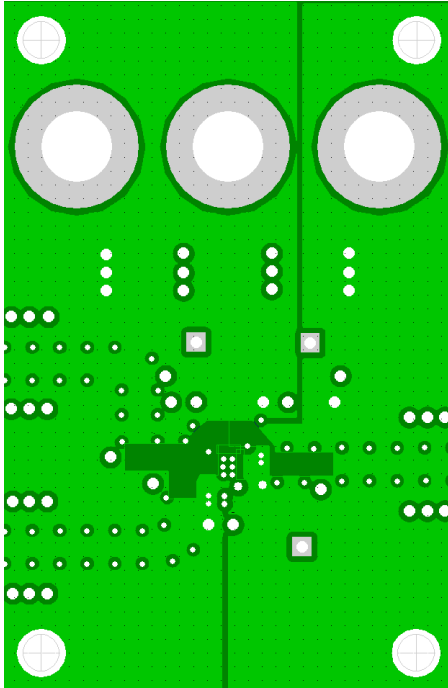


Figure 98. THS4271/THS4275 EVM Board Layout (Third Layer, Power)

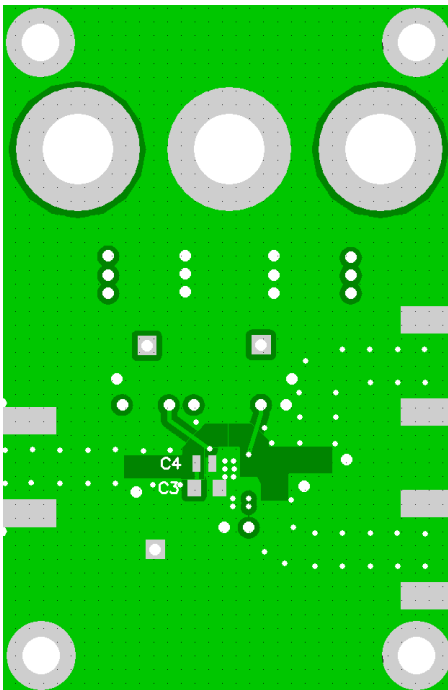


Figure 99. THS4271/THS4275 EVM Board Layout (Bottom Layer)

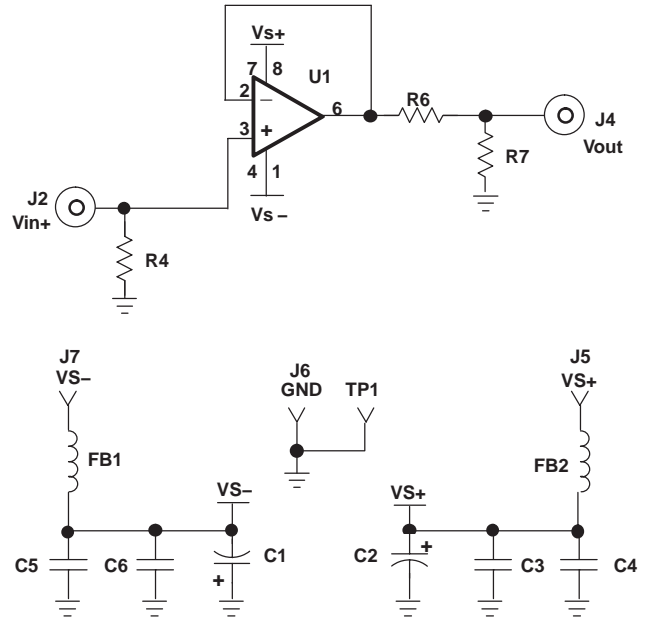


Figure 100. THS4271 Unity Gain EVM Circuit Configuration

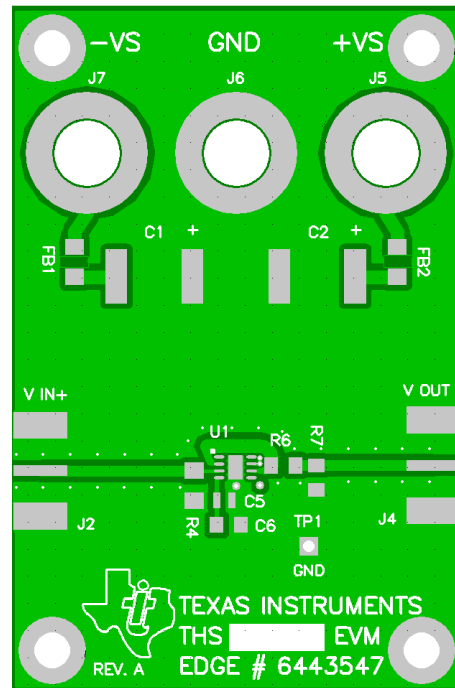


Figure 101. THS4271 Unity Gain EVM Board Layout (Top Layer)

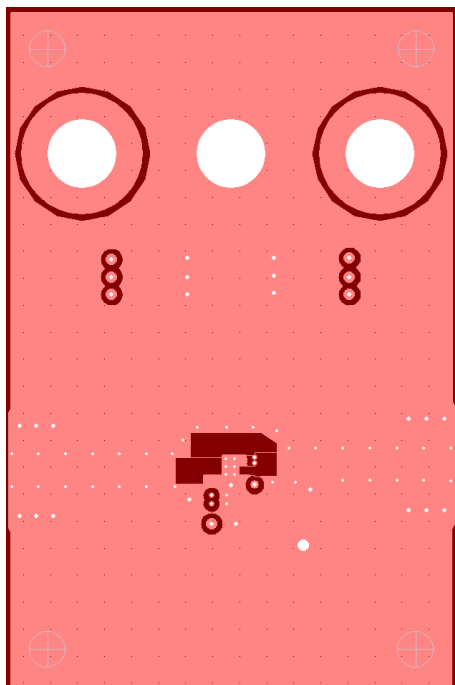


Figure 102. THS4271 Unity Gain EVM Board Layout (Second Layer, Ground)

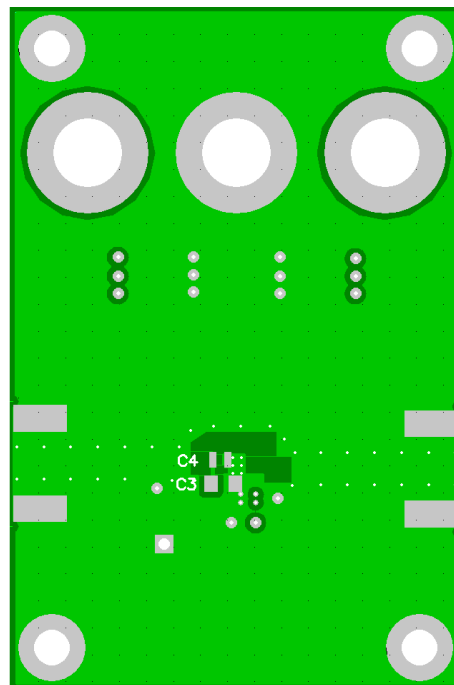


Figure 104. THS4271 Unity Gain EVM Board Layout (Bottom Layer)

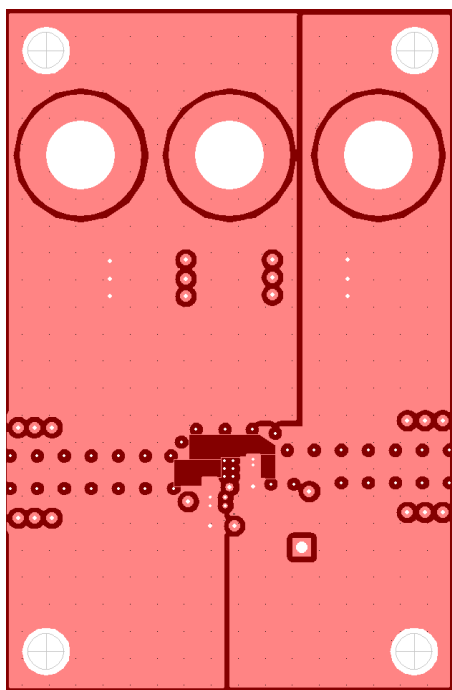


Figure 103. THS4271 Unity Gain EVM Board Layout (Third Layer, Power)

Computer simulation of circuit performance using SPICE is often useful when analyzing the performance of analog circuits and systems. This is particularly true for video and RF amplifier circuits where parasitic capacitance and inductance can have a major effect on circuit performance. A SPICE model for the THS4271 is available through either the Texas Instruments web site (www.ti.com). The PIC is also available for design assistance and detailed product information. These models do a good job of predicting small-signal ac and transient performance under a wide variety of operating conditions. They are not intended to model the distortion characteristics of the amplifier, nor do they attempt to distinguish between the package types in their small-signal ac performance. Detailed information about what is and is not modeled is contained in the model file itself.

ADDITIONAL REFERENCE MATERIAL

- *PowerPAD Made Easy*, application brief (SLMA004)
- *PowerPAD Thermally Enhanced Package*, technical brief (SLMA002)

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
THS4271D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DGK	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DGKG4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DNGG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4271DRBR	ACTIVE	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4271DRBRG4	ACTIVE	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4271DRBT	ACTIVE	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4271DRBTG4	ACTIVE	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4271DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DGK	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DGKG4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DGN	ACTIVE	MSOP-Power	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
		PAD						
THS4275DGNG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4275DRBR	ACTIVE	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4275DRBRG4	ACTIVE	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4275DRBT	ACTIVE	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4275DRBTG4	ACTIVE	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4275DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
THS4271DGKR	MSOP	DGK	8	2500	330.0	12.4	5.2	3.3	1.6	8.0	12.0	Q1
THS4271DGNR	MSOP-Power PAD	DGN	8	2500	330.0	12.4	5.2	3.3	1.6	8.0	12.0	Q1
THS4271DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
THS4271DRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
THS4271DRBT	SON	DRB	8	250	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
THS4275DGKR	MSOP	DGK	8	2500	330.0	12.4	5.2	3.3	1.6	8.0	12.0	Q1
THS4275DGNR	MSOP-Power PAD	DGN	8	2500	330.0	12.4	5.2	3.3	1.6	8.0	12.0	Q1
THS4275DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
THS4275DRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
THS4275DRBT	SON	DRB	8	250	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS

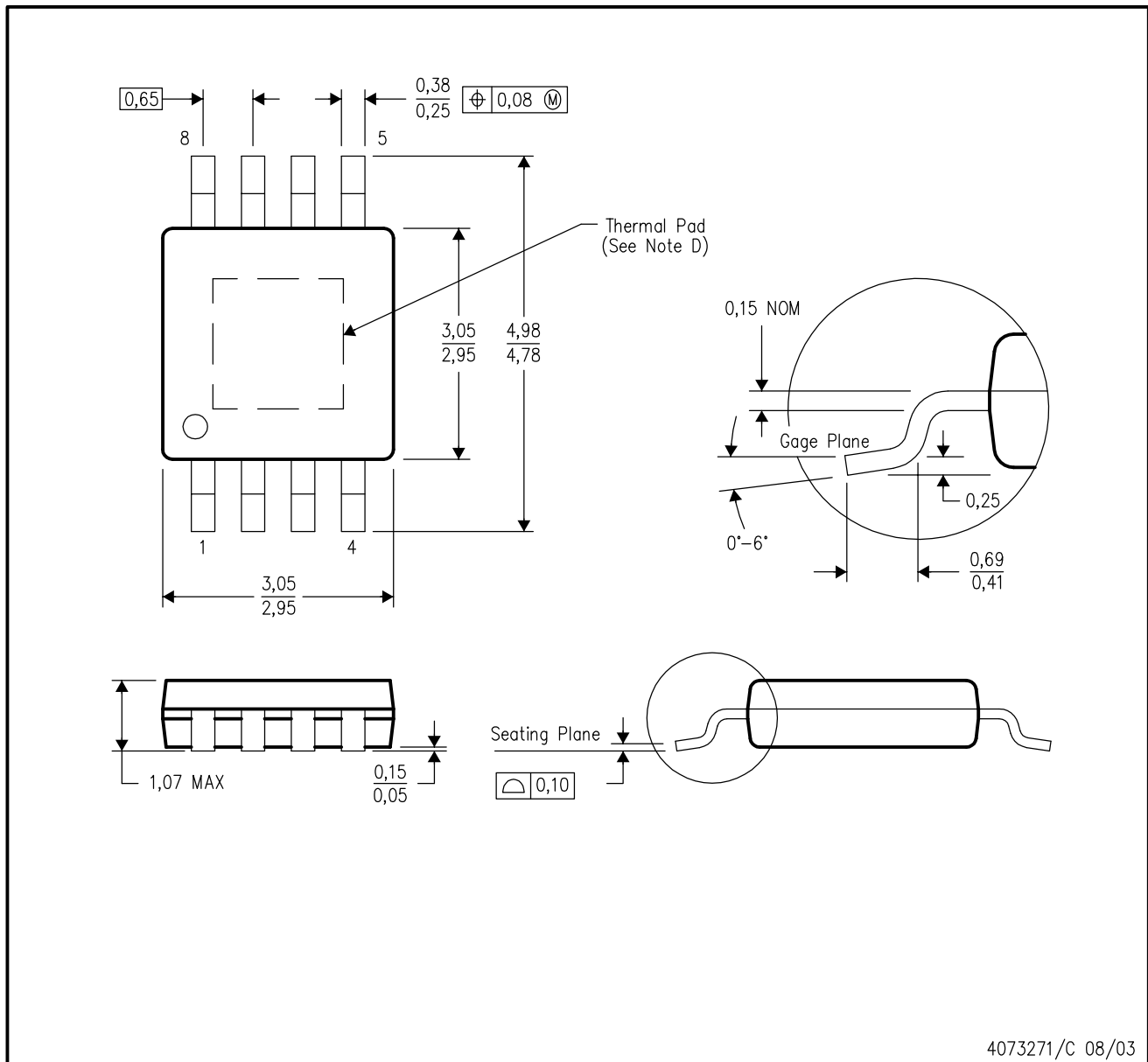


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
THS4271DGKR	MSOP	DGK	8	2500	338.1	340.5	21.1
THS4271DGNR	MSOP-PowerPAD	DGN	8	2500	338.1	340.5	21.1
THS4271DR	SOIC	D	8	2500	346.0	346.0	29.0
THS4271DRBR	SON	DRB	8	3000	340.5	333.0	20.6
THS4271DRBT	SON	DRB	8	250	340.5	333.0	20.6
THS4275DGKR	MSOP	DGK	8	2500	338.1	340.5	21.1
THS4275DGNR	MSOP-PowerPAD	DGN	8	2500	338.1	340.5	21.1
THS4275DR	SOIC	D	8	2500	346.0	346.0	29.0
THS4275DRBR	SON	DRB	8	3000	340.5	333.0	20.6
THS4275DRBT	SON	DRB	8	250	340.5	333.0	20.6

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



4073271/C 08/03

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - Falls within JEDEC MO-187

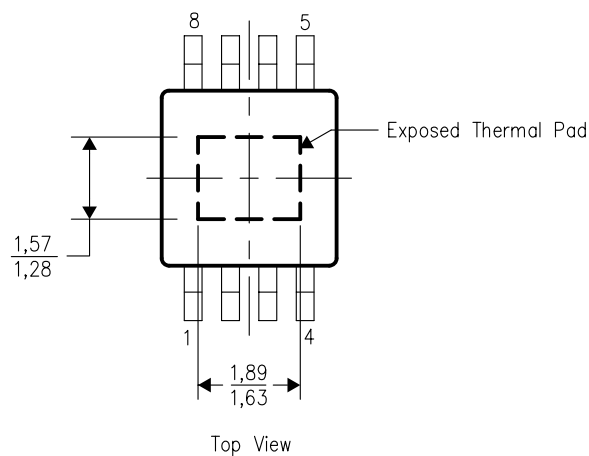
PowerPAD is a trademark of Texas Instruments.

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

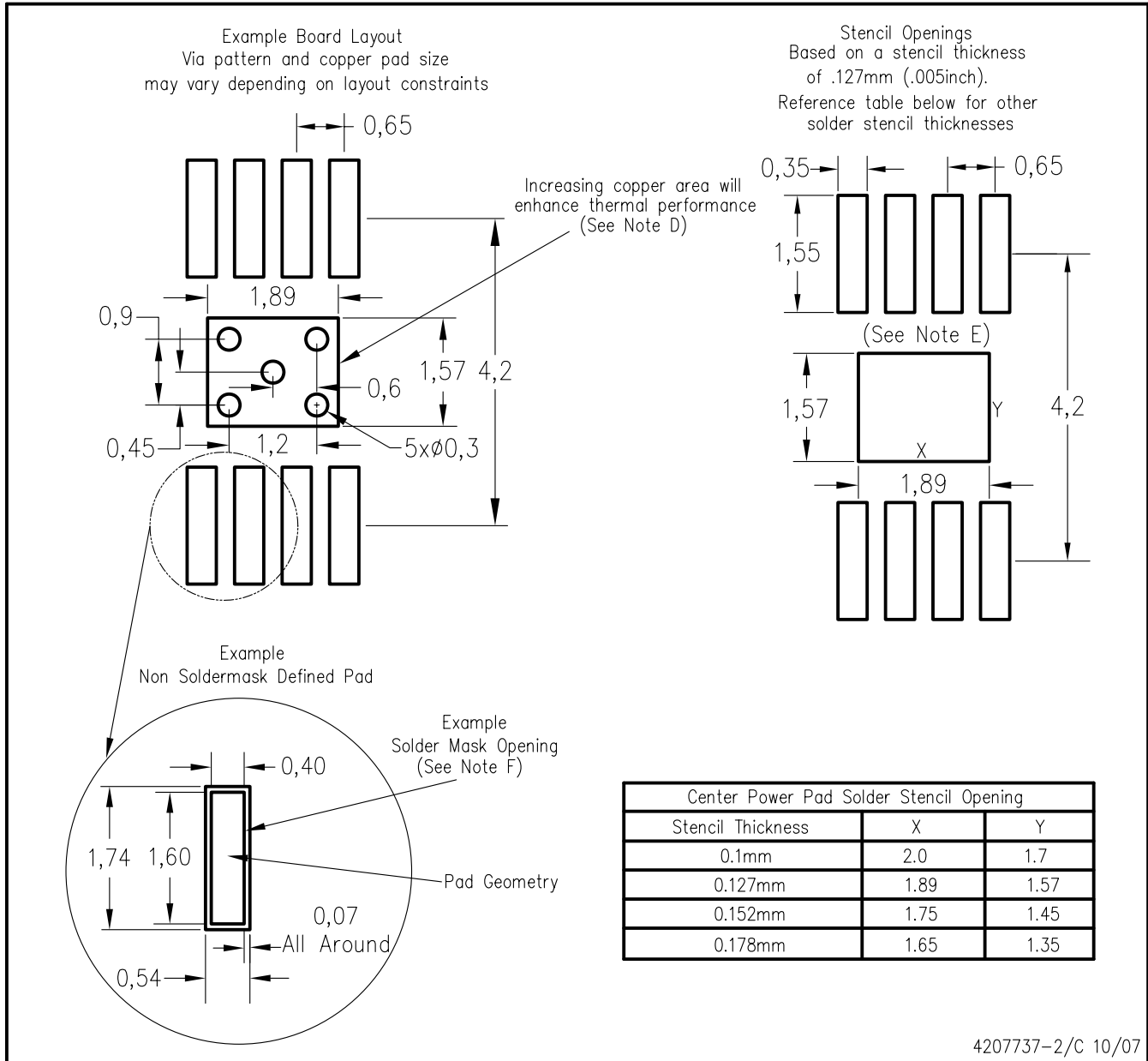
The exposed thermal pad dimensions for this package are shown in the following illustration.



NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

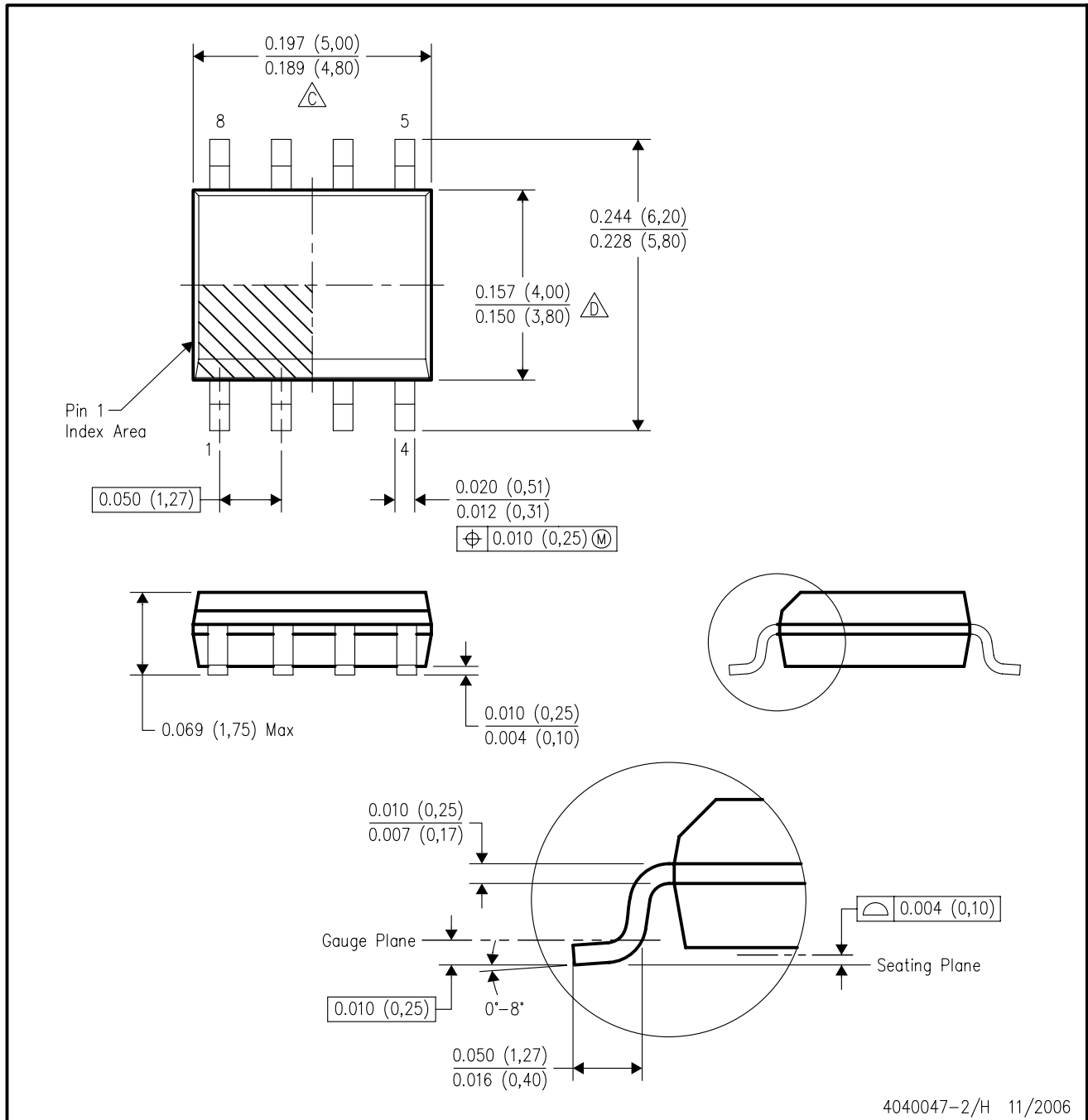
DGN (R-PDS0-G8) PowerPAD™



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G8)

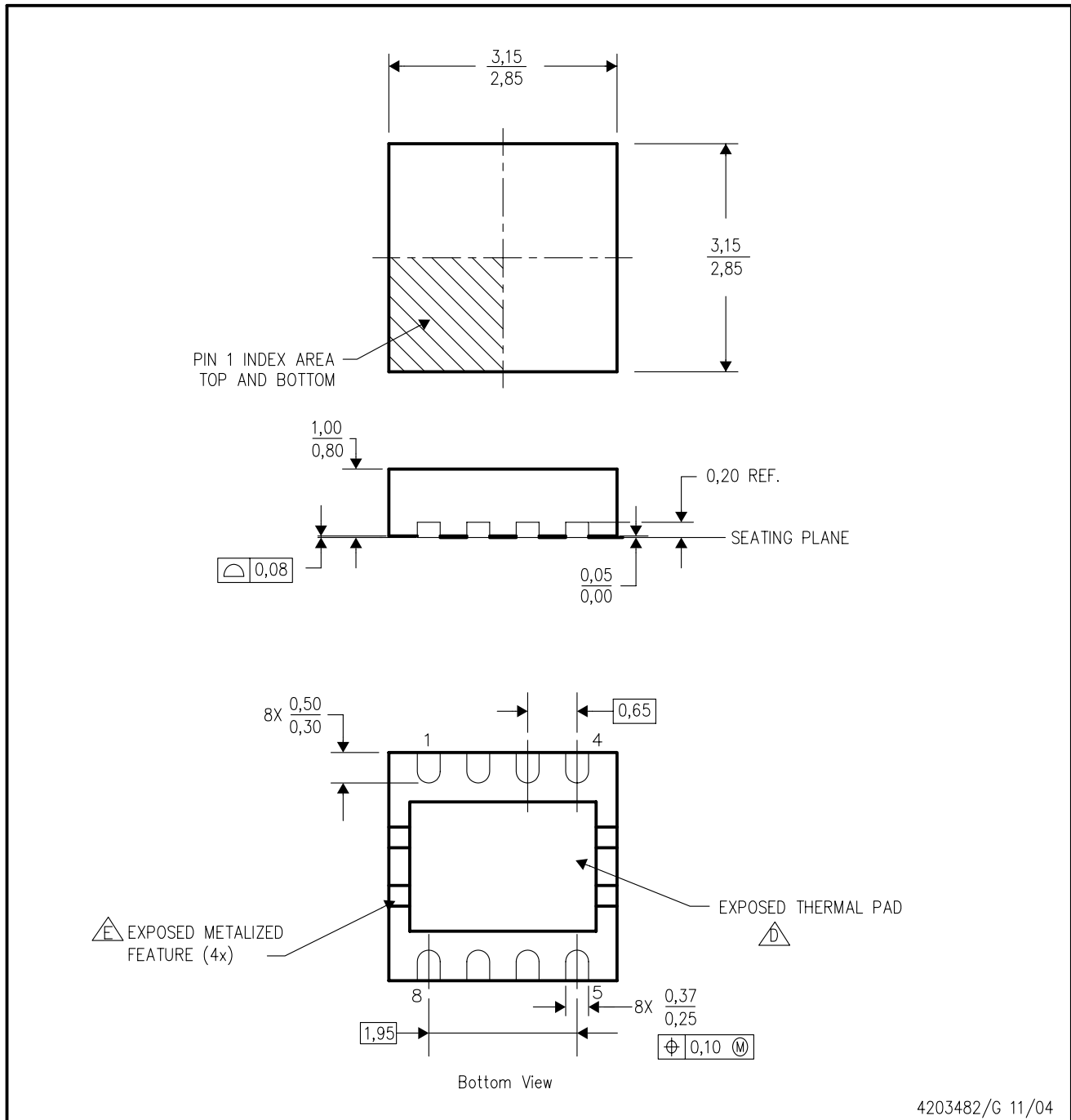
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

DRB (S-PDSO-N8)

PLASTIC SMALL OUTLINE



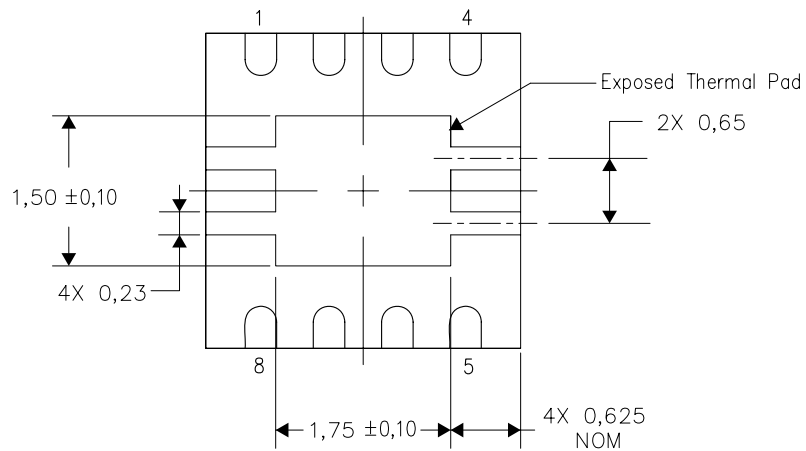
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Small Outline No-Lead (SON) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
 - Metalized features are supplier options and may not be on the package.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

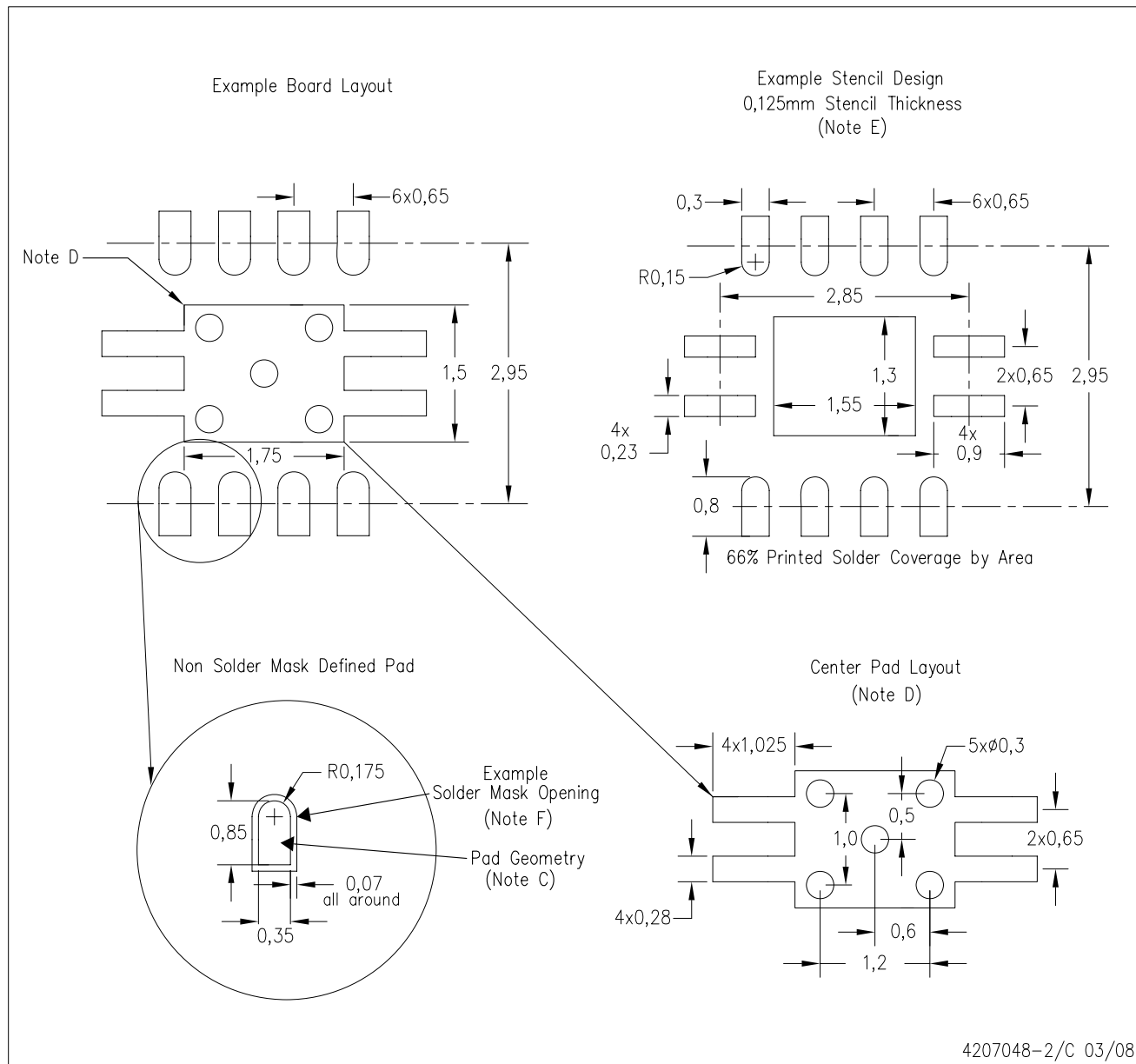


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

DRB (S-VSON-N8)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for solder mask tolerances.

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated